

MSC8156 Advanced Mezzanine Card User's Manual

MSC8156AMCUM
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About This Book

This user manual defines the functionality of MSC8156 AMC. MSC8156 AMC is a complete advanced mezzanine card development system for engineers developing applications and systems for the MSC8156 digital signal processor.

Audience

It is assumed that the reader understands operating systems, microprocessor system design, and the basic principles of RISC processing.

Organization

Following is a summary and a brief description of the chapters of this user manual:

- [Chapter 1, “Overview,”](#) provides a detailed description of components, working configuration, features, external connectors, characteristics and specifications, hardware preparation and installation, and memory map of MSC8156 AMC.
- [Chapter 2, “Controls and Indicators,”](#) elucidates on controls and indicators, such as switches, jumpers, LEDs, and push button switches of MSC8156 AMC processor board.
- [Chapter 3, “Functional Description,”](#) describes the various functional blocks in the MSC8156 AMC, how they are used, and the available configuration options.

Suggested Reading

This section lists additional reading that provides background for the information in this manual as well as general information about the architecture.

Related Documentation

Freescale documentation relevant to this kit is available from the following sources:

- *MSC8156 Technical Data Sheet*
- *MSC8156 Reference Manual*
- *MSC8156 AMC Hardware Getting Started Guide*
- *MSC8156 Mezzanine Hardware Design Description*
- *AMC Base Card Hardware Design Description*

Additional literature is published as new processors become available. For a current list of documentation, refer to www.freescale.com.

Additional documentation relevant to this kit is available from the following sources:

- PICMG AMC.0 R2.0 “Advanced Mezzanine Card Base Specification”

- PICMG 2.15 “PCI Telecom Mezzanine/Carrier Card Specification”

Conventions

This document uses the following notational conventions:

cleared/set	When a bit takes the value zero, it is said to be cleared; when it takes a value of one, it is said to be set.
mnemonics	Instruction mnemonics are shown in lowercase bold
<i>italics</i>	Italics indicate variable command parameters, for example, bcctrx
	Book titles in text are set in italics
	Internal signals are set in lowercase italics, for example, <u>core int</u>
0x0	Prefix to denote hexadecimal number
0b0	Prefix to denote binary number
rA, rB	Instruction syntax used to identify a source GPR
rD	Instruction syntax used to identify a destination GPR
REG[FIELD]	Abbreviations for registers are shown in uppercase text. Specific bits, fields, or ranges appear in brackets. For example, MSR[LE] refers to the little-endian mode enable bit in the machine state register.
x	In some contexts, such as signal encodings, an unitalicized x indicates a don't care.
<i>x</i>	An italicized <i>x</i> indicates an alphanumeric variable
<i>n</i>	An italicized <i>n</i> indicates a numeric variable
¬	NOT logical operator
&	AND logical operator
	OR logical operator
	Concatenation, for example, TCR[WPEXT] TCR[WP]
—	Indicates a reserved bit field in an e500 register. Although these bits can be written to as ones or zeros, they are always read as zeros.

Signal Conventions

<u>OVERBAR</u>	An overbar indicates that a signal is active-low
<i>lowercase_italics</i>	Lowercase italics is used to indicate internal signals
lowercase_plaintext	Lowercase plain text is used to indicate signals that are used for configuration.

Acronyms and Abbreviations

Table i contains acronyms and abbreviations used in this document.

Table i. Acronyms and Abbreviations

Term	Meaning
AMC	Advanced mezzanine card (AdvancedMC™)
ATCA	Advanced telecommunications computing architecture
BDM	Background debug mode
BTS	Base transceiver station
CPLD	Complex programmable logic device
DIP	Dual in-line package
DNP	Do not populate
DSP	Digital signal processor
EEPROM	Electrically erasable, programmable read-only memory
FPGA	Field programmable gate array
FRU	Field replaceable unit
GETH	Gigabit Ethernet
HSC	High-speed connector
HW	Hardware
I ² C	Inter-integrated circuit
IPMB-L	Intelligent platform management bus-local
IPMC(V)	Intelligent platform management controller (voltage)
IPMI	Intelligent platform management interface
LTE	Long-term evolution
MMC	Module management controller
MTCA	Microtelecommunications computing architecture (MicroTCA™)
RCW	Reset configuration word
sRIO	Serial rapid IO
UART	Universal asynchronous receiver/transmitter
UEC	UCC Gigabit Ethernet controller
WIMAX	Worldwide interoperability for microwave access
xTCA	ATCA, uTCA, picoTCA chassis or equivalent



Chapter 1

Overview

Freescall's MSC8156 AMC is a complete advanced mezzanine card (AMC) development system for engineers developing applications and systems for the MSC8156 digital signal processor (DSP).

1.1 Introduction

The MSC8156 AMC is a high-density, single-width, full-height advanced mezzanine card DSP platform based around three MSC8156 DSPs. The MSC8156 delivers a high level of performance and integration, combining six, fully programmable SC3850 DSP cores, each running at 1 GHz.

Each MSC8156 has 1 Gbyte of associated 64-bit-wide DDR3 memory split into two banks. For data plane applications, high-throughput 3.125-GHz $\times 4$ RapidIO links connect the three MSC8156s to each other and to the data backplane through IDT's high-bandwidth 10-port ($\times 4$) CPS10Q SRIO switch. Data or control plane applications are handled by the 1-Gbyte Ethernet interfaces. Two 1000 Base-X 1-Gbyte interfaces connect the backplane to the MSC8156s through an Ethernet switch. Each MSC8156 has 2-Gbyte reduced gigabit media-independent interface (RGMII) connected to the Ethernet switch. Two additional gigabit Ethernet interfaces are provided at the front panel for test and control. For bootstrap purposes, a common serial I²C bus and EEPROM is connected between the MSC8156s. Board control and hot swapping are provided by the Pigeon-Point-based module management controller (MMC). To facilitate debug and development, a number of headers and connectors have been offloaded to an expansion card.

MSC8156 AMC has been designed around a mezzanine concept to aid future development. The mezzanines provide the system building blocks, enabling future AMC prototyping systems to be quickly realized.

Figure 1-1 shows the block diagram of MSC8156 AMC.

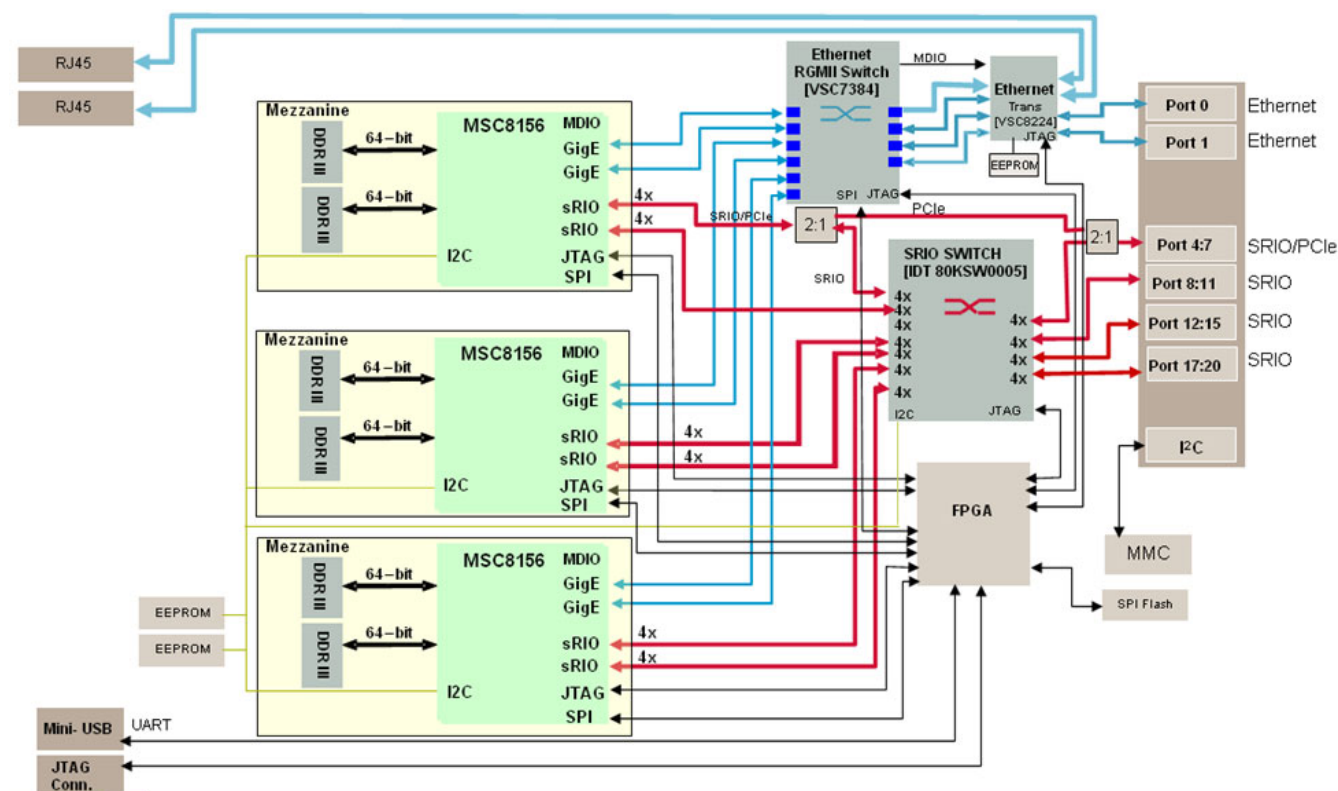


Figure 1-1. MSC8156 AMC Block Diagram

1.2 Working Configuration

MSC8156 AMC can be configured in any of the following two modes:

- Standard AMC mode
- Stand-alone mode

1.2.1 Standard AMC Mode

Freescale recommends running the MSC8156 AMC in an ATCA, microTCA, picoTCA chassis, or equivalent (xTCA). This enables the correct power and air flow to be delivered to the board. The MSC8156 AMC has been designed to work in any chassis that accepts full-height modules.

1.2.2 Stand-Alone Mode

Although not a standard AMC configuration, the MSC8156 AMC runs stand-alone. An optional external 12-V power supply barrel connector is used for stand-alone operation. (The MSC8156ADS power supply can be used here.) Note that this connector violates the AMC component envelope. For further details on running the MSC8156 AMC in stand-alone mode, contact the local FAE.

NOTE

In stand-alone mode, ensure that adequate cooling is provided for the board to prevent board damage.

1.3 Features

The main features of MSC8156 AMC are as follows:

- Form factor
 - Single-width AMC size, full-height module
- Three MSC8156 DSPs
 - Powerful and flexible DSP with six SC3850 Starcore® cores at 1 GHz and up to 48,000 MMACS per device
 - Multiaccelerator platform engine for baseband (MAPLE-B)
 - Programmable Turbo and Viterbi decoders
 - Two banks of 512-Mbyte 64-bit DDR3 800 per MSC8156
- SerDes connectivity
 - Full-SRIO connectivity among MSC8156s, and between MSC8156s and backplane ports
 - Each MSC8156 with two x4 3.125-GHz SRIO ports connected to SRIO switch
 - Four backplane ports from port lanes [4:7], [8:11], [12:15], and [17:20] connected to SRIO switch
 - Option to route SRIO/PCIe from single MSC8156 to backplane port [4:7], bypassing SRIO switch
- Ethernet connectivity
 - Each MSC8156 with two RGMII ports connected to Ethernet switch
 - 1000 Base-X gigabit Ethernet from backplane ports [0] and [1] routed to MSC8156s through Ethernet switch
 - Two gigabit Ethernet interfaces routed to front panel RJ45s
- Peripherals
 - MSC8156 UART interfaces multiplexed through the FPGA to a single mini-USB B connector on the front panel through a UART/USB transceiver
 - I²C bus connecting MSC8156s for boot and configuration
 - Serial peripheral interface (SPI) bus connecting MSC8156s to on-board serial flash
- Booting ability
 - MSC8156 boot through SRIO over backplane
 - MSC8156 boot from on-board I²C EEPROM
- Debugging ability
 - JTAG header provided for MSC8156 access
 - Expansion card enabling access to FPGA and MMC headers
 - Two DIL switches provide configuration and debug options
- MMC
 - Hot swapping
 - FRU storage
 - Status LEDs

- Temperature and voltage monitoring
- Power supply
 - 12-V payload and 3.3-V IPMCV, provided from AMC edge connector
 - 12-V barrel connector (optional) for stand-alone work
 - On-board voltage requirements are generated through DC–DC voltage regulators

1.4 External Connectors

The MSC8156 AMC interconnects with external devices through the following set of connectors (see [Figure 1-2](#) and [Figure 1-3](#)):

1. AMC connector for connecting to xTCA backplanes
2. MSC8156 OnCE™ 14-pin debug connector
3. Mini-USB type B (UART)
4. RJ45 Ethernet connector
5. Integrated RJ45 and USB type A (USB is not used in MSC8156 AMC)
6. Stand-alone power connector (optional)
7. Expansion connector giving access to the following:
 - a) FPGA programming header
 - b) MMC programming header
 - c) MMC UART payload header
 - d) MMC UART serial debug interface header

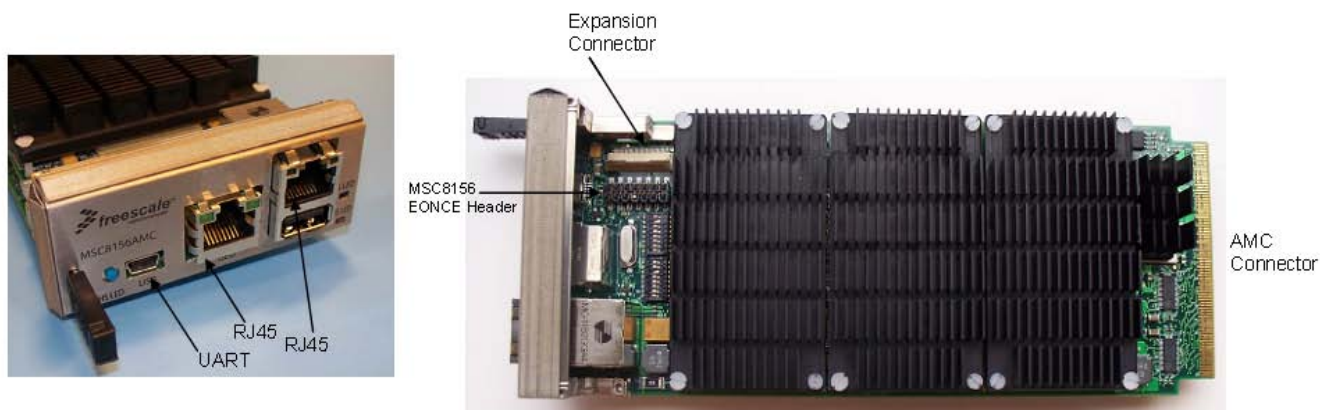


Figure 1-2. MSC8156 AMC External Connections

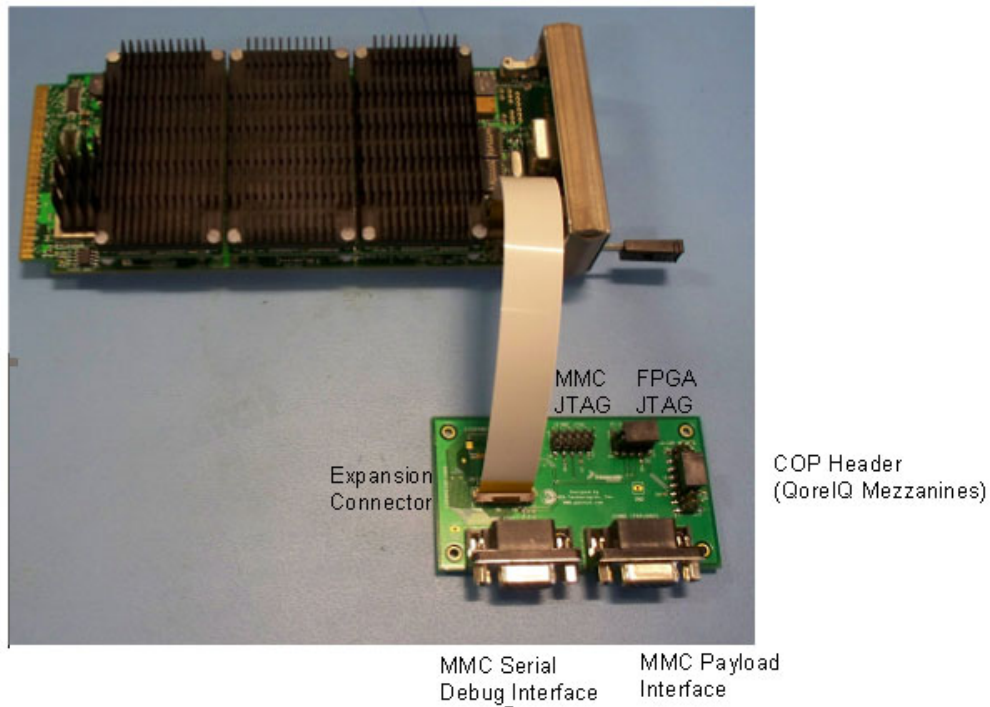


Figure 1-3. MSC8156 AMC Expansion card

1.5 Specifications

Table 1-1 describes the environmental specifications that should be adhered to when operating the MSC8156 AMC.

Table 1-1. Environmental Specifications

Characteristics	Specifications
Power requirements	No external power supply for AMC mode powered from xTCA chassis In stand-alone mode, the recommended PSU should supply 12 V at 5 A
Operating temperature	0–70 °C
Storage temperature	–25 °C to 85 °C
Relative humidity	5–90% (noncondensing)
Dimensions	Single-width AMC form factor Length = 180.6 mm Width = 73.5 mm PCB thickness = 1.6 mm

Table 1-2. MSC8156 AMC Top Level Specification

Characteristics	Specifications
MSC8156	Six cores each running at 1 GHz

Table 1-2. MSC8156 AMC Top Level Specification

Memory (per MSC8156)	Internal M3	1 Mbyte of shared M3
	DDR	1 Gbyte of 64-bit-wide DDR3 800 split between two memory banks
Memory (per AMC)	I ² C EEPROM	64-Kbyte serial EEPROM for boot code
	SPI Flash	16 Mbyte of SPI Flash
Com Ports	GETH	2 RJ45 ports at front panel 2 1000 Base-X at backplane
	SRIO	2 SRIO ports (x1/x4) Hardware configurable to 1.25, 2.5, and 3.125 GHz data rates
	UART	RS232 transceiver allows data exchange at 115 Kbps

1.6 Hardware Preparation and Installation

This chapter provides unpacking instructions, hardware preparation, and installation instructions for the MSC8156 AMC processor board. For more details on hardware preparation, refer to *MSC8156 AMC Hardware Getting Started Guide*.

1.6.1 Unpacking Instructions

Perform the following step-by-step instructions to unpack the equipment:

1. Unpack the equipment from shipping carton.
2. Refer to packing list and verify that all items are present.
3. Save packing material for storing and reshipping of the equipment.

NOTE

If the shipping carton is damaged upon receipt, request carrier’s agent to be present during unpacking and inspection of the equipment.

CAUTION

Avoid touching the areas of integrated circuitry; static discharge can damage circuits.

1.6.2 Installation Instructions

Do the following in the order indicated to install the MSC8156 AMC processor board properly:

1. Verify that jumpers and switches are in default positions (see [Chapter 2, “Controls and Indicators,”](#) for a list of default positions).
2. Connect external cables as per your requirement (see [Section 1.4, “External Connectors,”](#) for more details).
3. Insert the board into the carrier or chassis as per the specific chassis operating instructions.
4. Switch on the power to the chassis.

5. Check for completion of the reset sequence indicated by the LEDs. See [Chapter 2, “Controls and Indicators,”](#) for more information.
 - a) When the AMC is powered up (hot swap handle inserted), the blue LED on the front panel flashes and then stays off .
 - b) The five LEDs D1–D5 flash on and then go off. D5 starts blinking to indicate the board is powered up and alive.
 - c) Any Ethernet activity is indicated by D4.
6. Hit the front panel push button to reset the board.
7. Hit the reset button on the MSC8156 AMC secondary side to reset the board.
8. Operate CodeWarrior to verify that the board has been installed properly.

1.7 Memory Map

Each of the three MSC8156s has an identical memory map as described in [Table 1-3](#).

Table 1-3. MSC8156 Memory Map

Address Range	Memory Type	Device Name	Size
0x40000000–0x5FFFFFFF	DDR3 (Memory Controller 1)	4× 16-bit-wide MT41J64M16LA-15E	512 M
0x60000000–0x7FFFFFFF	Reserved	Empty space	512 M
0x80000000–0x9FFFFFFF	DDR3 (Memory Controller 2)	4× 16-bit-wide MT41J64M16LA-15E	512 M
0xA0080000–0xBFFFFFFF	Reserved	Empty space	512 M
0xC0000000–0xC0107FFF	M3 memory	Internal	1 M + 32 K
0xC0108000–0xFECFFFFF	Reserved	Empty space	511 M – 32 K
0xFED00000–0xFEDFFFFF	MAPLE-B	Internal	1 M
0xFEE00000–0xFEE3FFFF	QUICC engine subsystem	Internal	256 K
0xFEE40000–0xFEEFFFFF	Reserved (QUICC engine subsystem)	Internal	768 K
0xFEFE0000–0xFEFE17FFF	Boot ROM	Internal	96 K
0xFEFE18000–0xFEFFFFFFF	Reserved	Empty Space	928 K

Chapter 2 Controls and Indicators

This chapter describes controls and indicators for the MSC8156 AMC processor board, such as switches, jumpers, LEDs, and push button switches. [Figure 2-1](#) shows the locations of switches, jumpers, and push buttons, whereas [Figure 2-2](#) shows the locations of LEDs and push buttons for MSC8156 AMC.

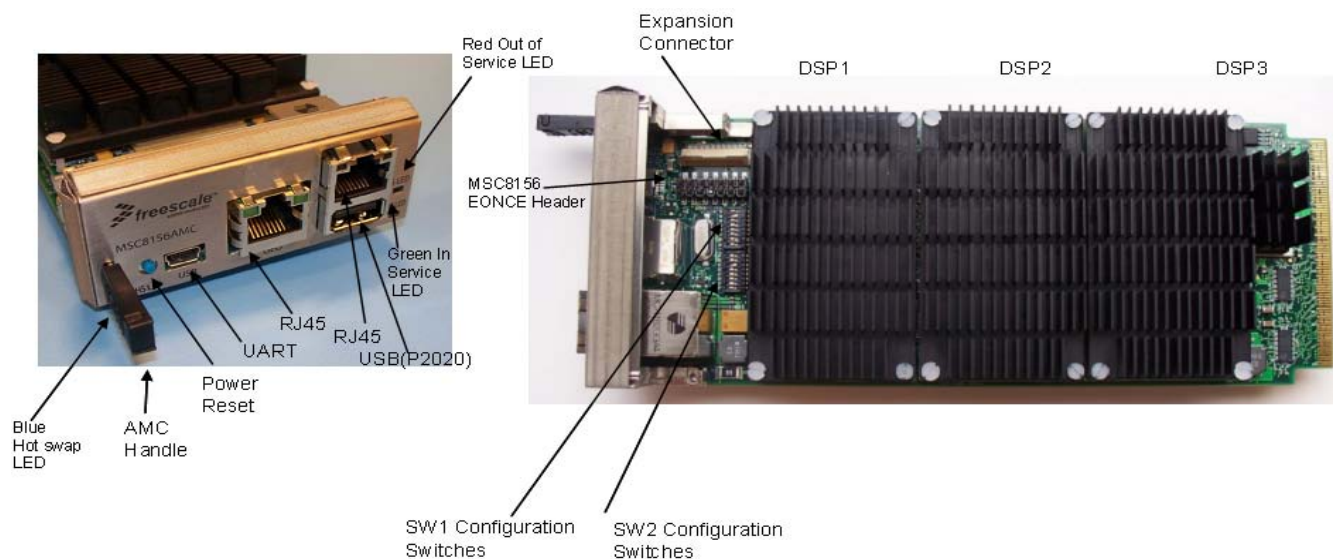


Figure 2-1. MSC8156 AMC Switches, Jumpers, and Push Button Locations

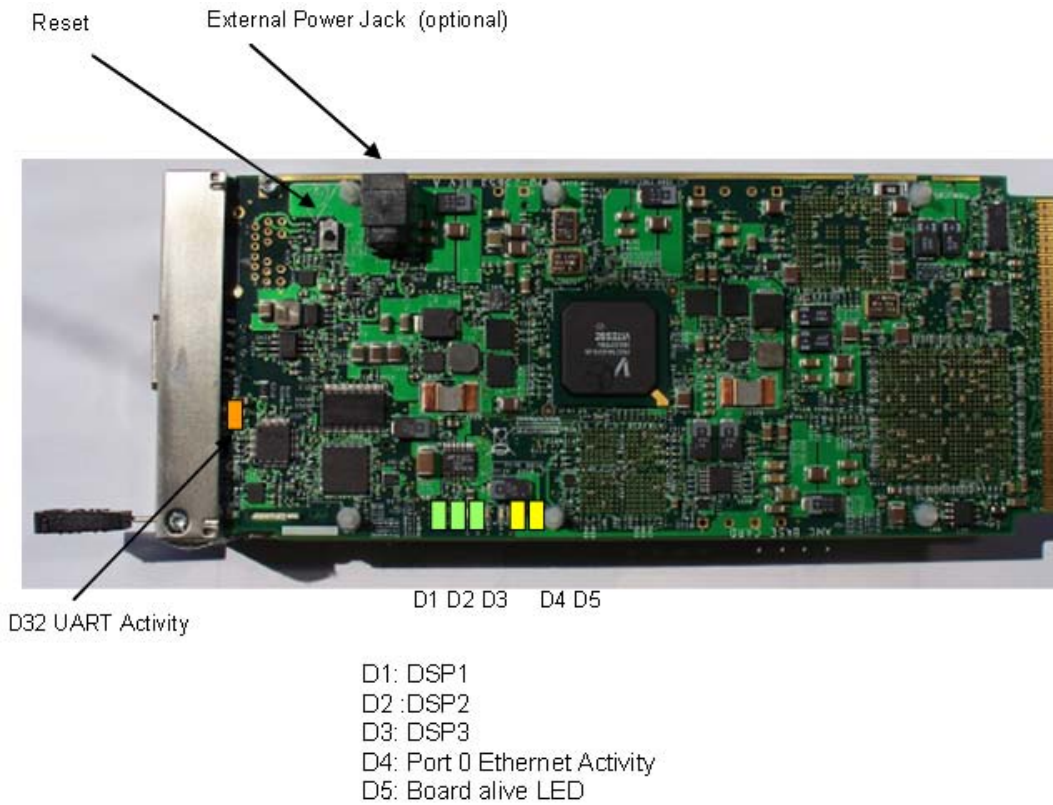


Figure 2-2. MSC8156 AMC LEDs and Push Button Locations

2.1 DIP Switches

Figure 2-3 shows the location on the board of the DIP switches and their default position. Table 2-1 describes the possible settings of the switches. Note that when the switch is ON, its value is zero. For more detailed description of the bits and fields, see the *MSC8156 Reference Manual*. Before changing any settings, check if the board is operational and ensure the default positions of the switches.

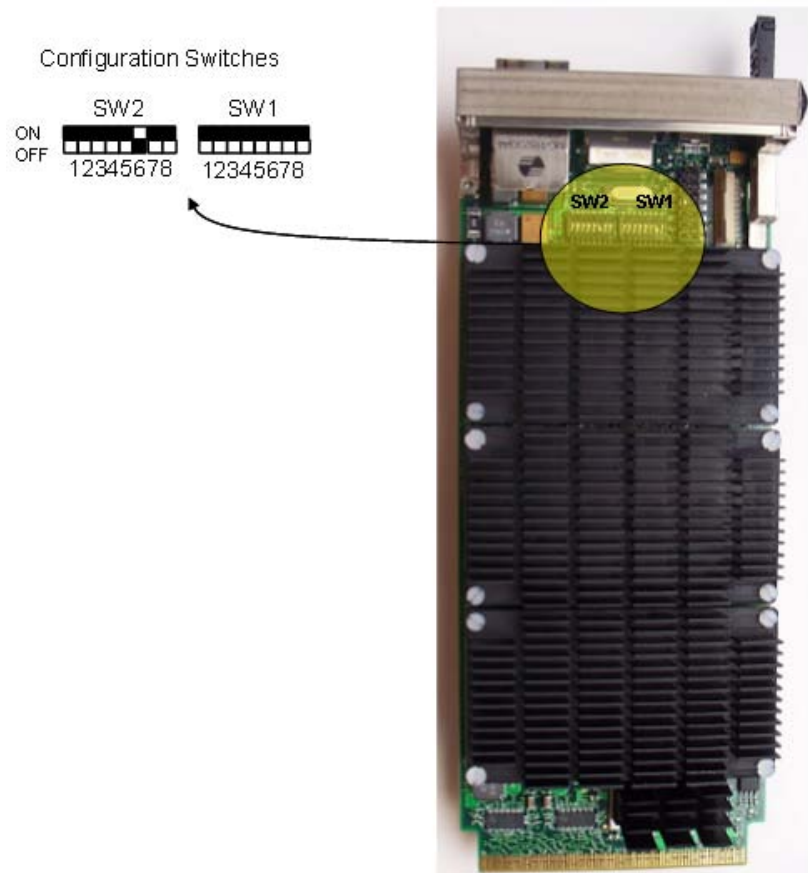


Figure 2-3. MSC8156 AMC—Default Switch Configuration

Table 2-1. DIP Switch Setting Descriptions

Switch Position	Settings	Comments
	SW2.1/SW2.2 ON ON ON OFF OFF ON OFF OFF	Select JTAG chain Full chain (x3) (default) DSP1 only DSP2 only DSP3 only
	SW2.3/SW2.4 ON ON ON OFF OFF ON OFF OFF	Select UART Ethernet switch (default) DSP1 DSP2 DSP3
	SW2.5/SW2.6 ON ON ON OFF OFF ON OFF OFF	SRIO switch frequency 1.25 GHz 3.125 GHz (default) 2.5 GHz Illegal mode
	SW2.7 ON OFF	DSP1 port 1 SerDes bypass Connects to SRIO switch (default) Connects direct to backplane port[4:7]
	SW2.8 ON OFF	Reset configuration word source I ² C, Boot port = SRIO (default) Hard coded option 1
	SW1.1 ON OFF	DSP debug mode Debug mode is off [EE0=0](default) Debug mode is on [EE0=1]
	SW1.2 ON OFF	CPS10Q boot mode Boot from EEPROM (default) Slave mode
	SW1.3 ON OFF	I ² C bus Separate CPS10Q and DSP I ² C bus (default) Combined CPS10Q and DSP I ² C bus
	SW1.4/SW1.5 ON ON ON OFF OFF ON OFF OFF	DSP1 SerDes clock source 125 MHz SRIO clock (default) Not applicable 100 MHz PCIe from backplane 100 MHz PCIe from on-board oscillator
	SW1.6 ON	Future use
	SW1.7 OFF ON	Working configuration Stand-alone mode xTCA chassis (default)
	SW1.8 ON	Future use

The MSC8156 clock settings, which are derived from SW2.8, are described in [Table 2-2](#).

Table 2-2. MSC8156 Clock Values

Clock	SW2.8 = ON (MHz)	SW2.8 = OFF (MHz)
CLKIN	100	100
PLL0	900	900
PLL1	1000	1000
PLL2	800	800
CLASS	900	900
DSP core subsystem	1000	1000
HSSI	333	333
QUICC engine	500	500
MAPLE	450	450
DDR controller 1	800	800
DDR controller 2	800	800
CLKOUT	100	80

2.2 LEDs

Table 2-3 describes the MSC8156 AMC processor board LEDs.

Table 2-3. LED Description

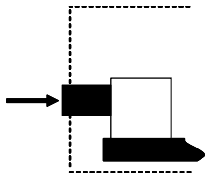
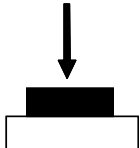
Description	Ref	Color	LED ON	LED OFF
DSP1	D1	Green	User programmable	User programmable
DSP2	D2	Green	User programmable	User programmable
DSP3	D3	Green	User programmable	User programmable
Port 0 Ethernet activity	D4	Yellow	Flash: Ethernet activity ON: Link	No link
Board alive indicator	D5	Yellow	Flash for board running	Payload power off
Front panel (blue hot swap)	D7	Blue	Hot swap status	Hot swap status
Front panel (red: out of service)	D8	Red	Fault condition	Normal operation
Front panel (green: in service)	D9	Green	Not implemented	Not implemented
UART activity	D32	Orange	Flash for activity	Off for no activity

Section 3.15, “MMC” describes in detail the function of the MSC8156 AMC front panel LEDs (D7–D9).

2.3 Push Buttons

Table 2-4 describes the MSC8156 AMC processor board push buttons.

Table 2-4. MSC8156 AMC Push Button Switches

<p>SW3 Board Reset</p>		<p>Pressing push button on the front panel resets the board</p>
<p>SW4 Board Reset</p>		<p>Pressing push button on the back of the board resets the board</p>

Chapter 3

Functional Description

This chapter describes the various functional blocks in the MSC8156 AMC, how they are used, and the options available for their configuration.

3.1 JTAG Debug Interface

Each of the MSC8156's JTAG debug ports is connected to the FPGA. The FPGA then combines them into a chain based on the switch SW2.1 and SW2.2 selection, as shown in [Figure 3-2](#). A single JTAG connector (Samtec TSM-107-01-S-DV-P) on the board enables to connect to the MSC8156s (see [Figure 3-1](#)).

The signals available on the JTAG connector are as follows:

- TMS: This signal is pulled up so that after reset 5, TCK clocks put the TAP into the test logic reset state.
- TSRT: The reset signal is pulled low to force the JTAG into reset by default.
- TCK: The clock signal is pulled low to save power in low-power stop mode.
- TDI: The input signal is pulled high to save power in low-power stop mode. All JTAG ports have a weak internal TDI pull up.
- TDO: The output signal is pulled high.
- HRESET: This signal is pulled high and connects to the FPGA.

[Figure 3-1](#) defines the pin out of the connector.

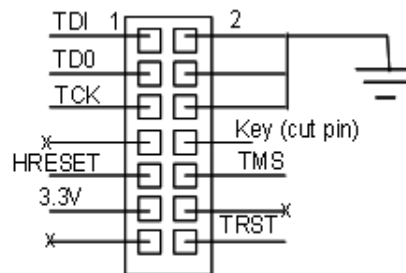


Figure 3-1. JTAG Header for MSC8156

The JTAG chain listing used with the CodeWarrior tools is described in [Appendix A, “JTAG Configuration File Listing.”](#)

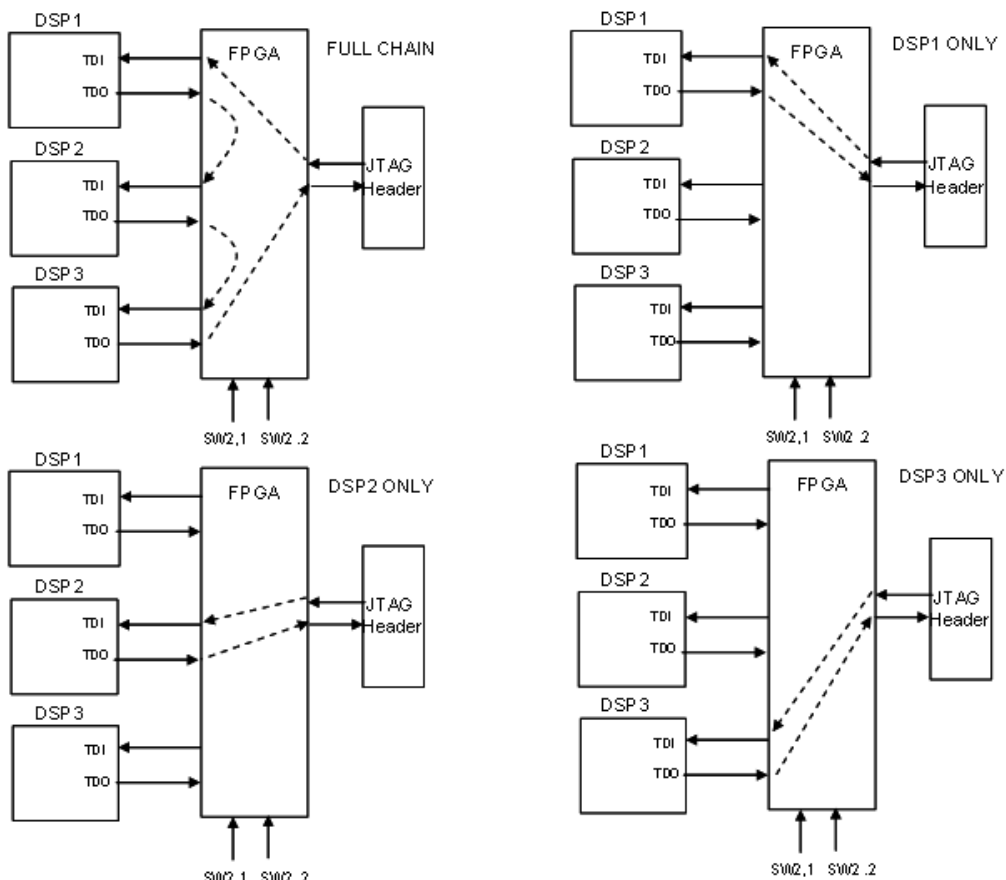


Figure 3-2. MSC8156 JTAG Chain Options

3.2 DDR3 Memory

Each DSP supports dual 64-bit DDR3 controllers. The MSC8156 AMC design utilizes both memory controllers attaching 512 Mbytes of DDR3 memory to each. The 512 Mbytes of DDR3 is constructed using 4 (1 Gbit) Micron MT41J64M16BLA-15E devices (8 Mbytes × 16 bits × 8 banks).

The DDR3-SDRAM is configured with 13-row address lines, 10-column address lines, and 8 banks. Control of each memory device is through the CS0 signal.

NOTE

EEC is not supported in the MSC8156 AMC design.

Complex DDR3 timing adaptation is available through the DDR clocking subsystem of the MSC8156. It supports the following:

1. Positioning of the DQS output signals relative to the data during writes to DDR memory
2. Sampling of input data from DDR memory
3. Synchronizing the incoming DDR data to the internal clock
4. Controlling the relationship between output data and CLK_OUT
5. Write leveling

6. Read leveling
7. ZQ calibration

The DDR3 interface operates with 1.5 V I/O and 0.75 VTT voltages, which are supplied from the AMC base card.

3.3 SerDes Configuration

Each DSP contains two ×4 SerDes ports, which are independent, configurable, multilane serial ports supporting serial RapidIO, PCIe, and SGMII.

The MSC8156 AMC is primarily an SRIO-based system, and both SerDes ports on all the three DSPs are configured for x4 serial RapidIO operation (referenced as SRIO0 and SRIO1) and connected to the SRIO switch. The one exception is the second SerDes port on DSP1, which can be configured to bypass the SRIO switch through high-speed SerDes multiplexers, and can be connected directly to the backplane ports [4:7]. This enables the specific port to be configured as SRIO or PCIe. This SRIO switch bypass option is controlled through switch SW2.7.

The SRIO switch connects four SRIO ports to the backplane. Two of these connections connect to the fat pipes section of the AMC connector ports [4:7] and ports [8:11]. The final two ports connect to the extended options backplane ports [12:15] and [17:20].

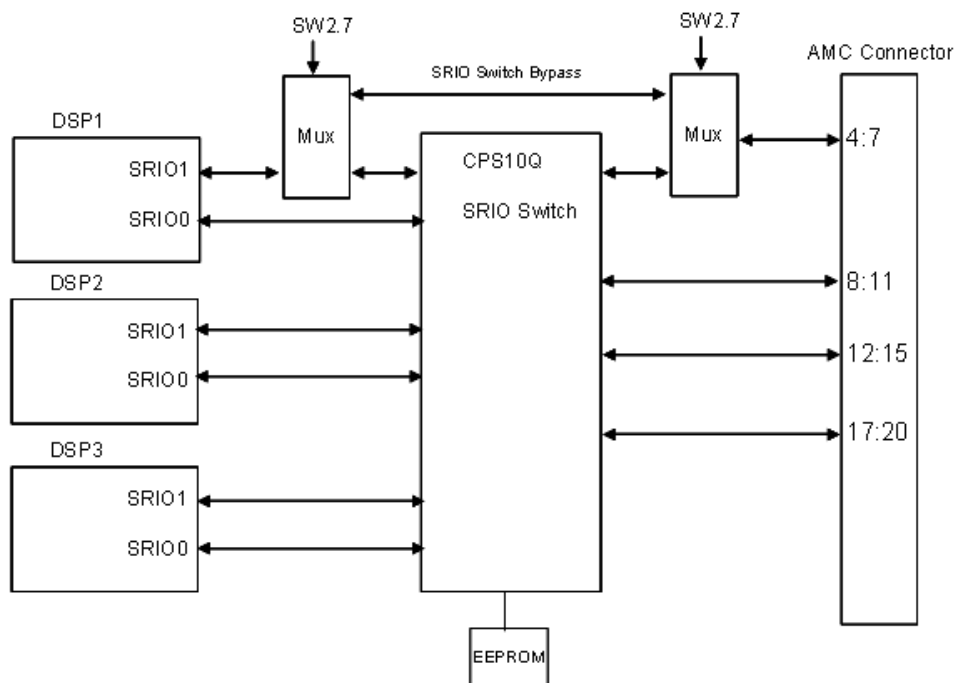


Figure 3-3. SerDes Configuration

3.3.1 SRIO Switch Configuration Modes

The CPS10Q SRIO switch can be configured through the following two different interfaces:

1. On power up through the I²C EEPROM (boot-master mode)

2. In band through a CPU/ DSP attached to one of the SRIO ports (boot-slave mode)

This is a switch configurable option (SW1.2), and the default is for the SRIO switch to be configured through its dedicated EEPROM on power up.

Table 3-1 details the configuration and port mappings of the SRIO switch following power up and configuration from the EEPROM. In boot-master mode, the CPS10Q powers up and reads configuration data from the EEPROM to configure all ports into Standard 4x mode. The frequency selection of the port among 1.25, 2.5, or 3.125 GHz speed is configured directly from switches SW2.5 and SW2.6.

Table 3-1. SRIO Switch Configuration (Boot-Master Mode)

Switch Lane	Port Mode	Port Number	End Point
3:0	Standard 4x	0	DSP2 SRIO0
7:4	Standard 4x	1	DSP2 SRIO1
11:8	Standard 4x	2	DSP3 SRIO0
15:12	Standard 4x	3	DSP3 SRIO1
16:19	Standard 4x	4	AMC SRIO1
23:20	Standard 4x	5	AMC SRIO2
27:24	Standard 4x	6	AMC SRIO0
31:28	Standard 4x	7	AMC SRIO3
35:32	Standard 4x	8	DSP1 SRIO0
36:39	Standard 4x	9	DSP1 SRIO1

In boot-slave mode, the SRIO switch receives no configuration data on power up and boots into a default state. In this mode, an SRIO host would be expected to configure the switch by maintenance transactions. Table 3-2 details the configuration of the switch in boot-slave mode.

Table 3-2. SRIO Switch Configuration (Boot-Slave Mode)

Switch Lane	Port Mode	Port Number	End Point
3:0	Standard 4x	0	DSP2 SRIO0
7:4	Standard 4x	1	DSP2 SRIO1
11:8	Standard 4x	2	DSP3 SRIO0
15:12	Standard 4x	3	DSP3 SRIO1
16	Enhanced 1x	4	AMC SRIO1
17	Enhanced 1x	5	
18	Enhanced 1x	6	
19	Enhanced 1x	7	
23:20	Standard 4x	8	AMC SRIO2
27:24	Standard 4x	9	AMC SRIO0

Table 3-2. SRIO Switch Configuration (Boot-Slave Mode) (continued)

Switch Lane	Port Mode	Port Number	End Point
31:28	Standard 4x	10	AMC SRIO3
35:32	Standard 4x	11	DSP1 SRIO0
36	Enhanced 1x	12	DSP1 SRIO1
37	Enhanced 1x	13	
38	Enhanced 1x	14	
39	Enhanced 1x	15	

Further details on the enhanced and standard SRIO switch operating modes can be obtained from the CPS10Q data sheet.

NOTE

The SRIO switch's EEPROM is factory configured over the I²C bus using an MSC8156 as the programmer.

3.3.2 SerDes Clocking

All MSC8156 SRIO SerDes blocks and the CPS10Q SRIO switch run with a fixed 156.25-MHz clock, enabling them to run at 3.125, 2.5, or 1.25 GHz depending on the selected SRIO speed. As DSP1 SRIO can be configured as PCIe, it has the additional option of running from either an on-board 100-MHz PCI clock or receiving a PCI clock direct from the backplane, as shown in [Figure 3-4](#). Switches SW1.5 and SW1.5 are used to select the clock through the clock multiplexers.

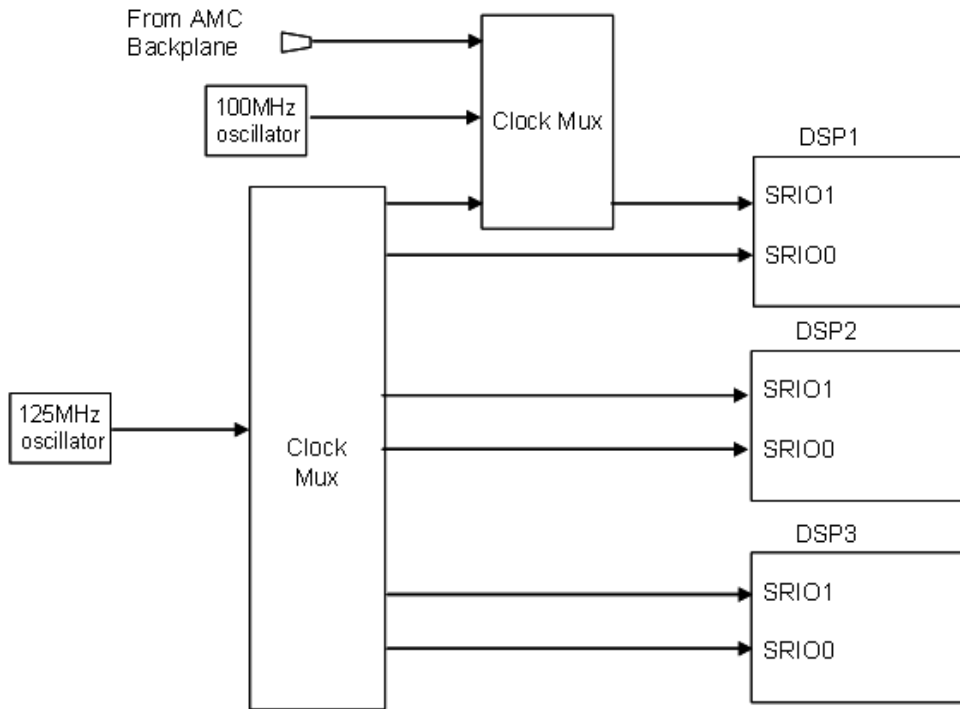


Figure 3-4. SerDes Clocking

3.3.3 PCIe Interface

The second DSP1 SerDes interface can be configured to run as PCIe by bypassing the SRIO switch and selecting the appropriate PCI clock. Running in PCIe also requires an MSC8156 AMC firmware update. For further details, contact the local Freescale FAE.

3.4 Gigabit Ethernet Ports

Each MSC8156 has 2-Gbit Ethernet controllers (GE1 and GE2) that can be configured independently for RGMII or SGMII operation. As the SGMII pins are multiplexed with the SRIO interface and the SerDes block is configured for SRIO operation, the RGMII interface is used for Ethernet.

A Vitesse VSC7384 12-port RGMII Ethernet switch provides the switching fabric among the DSPs, the AMC backplane ports, and front panel RJ45s. In total, it switches 10 Ethernet sources as shown in [Figure 3-5](#).

A Vitesse VSC8224 quad-port transceiver is used to switch from RGMII to 1000-Base-X on the backplane ports [0:1], and from RGMII to twisted pair or RJ45 on the front panel. The RJ45 contains integrated magnetics with two indicator LEDs.

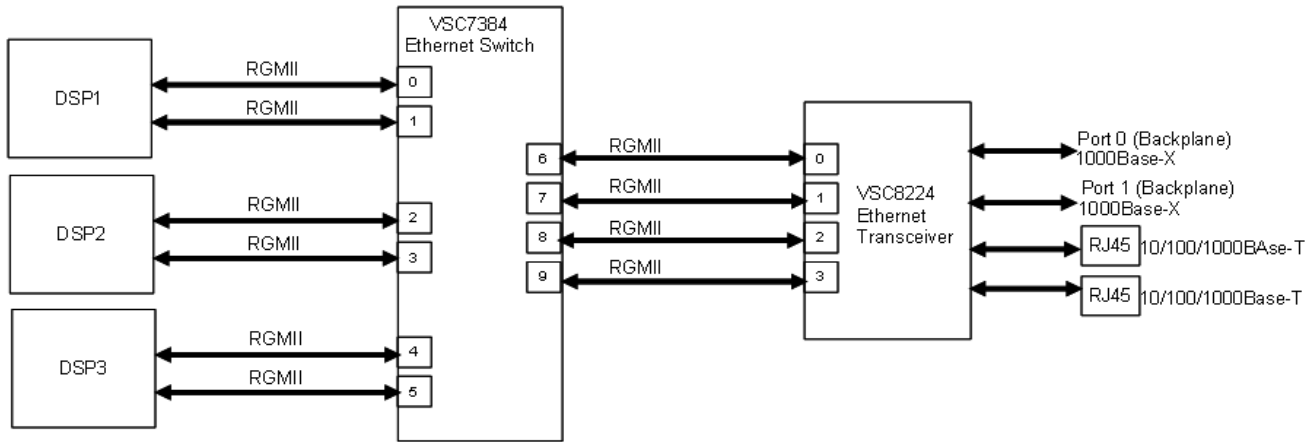


Figure 3-5. Ethernet Connectivity

3.4.1 Ethernet Switch Configuration

On power up, the FPGA configures the Ethernet switch’s internal microcontroller through its SPI . The Ethernet switch in turn configures the VSC8224 transceiver directly through its management interface.

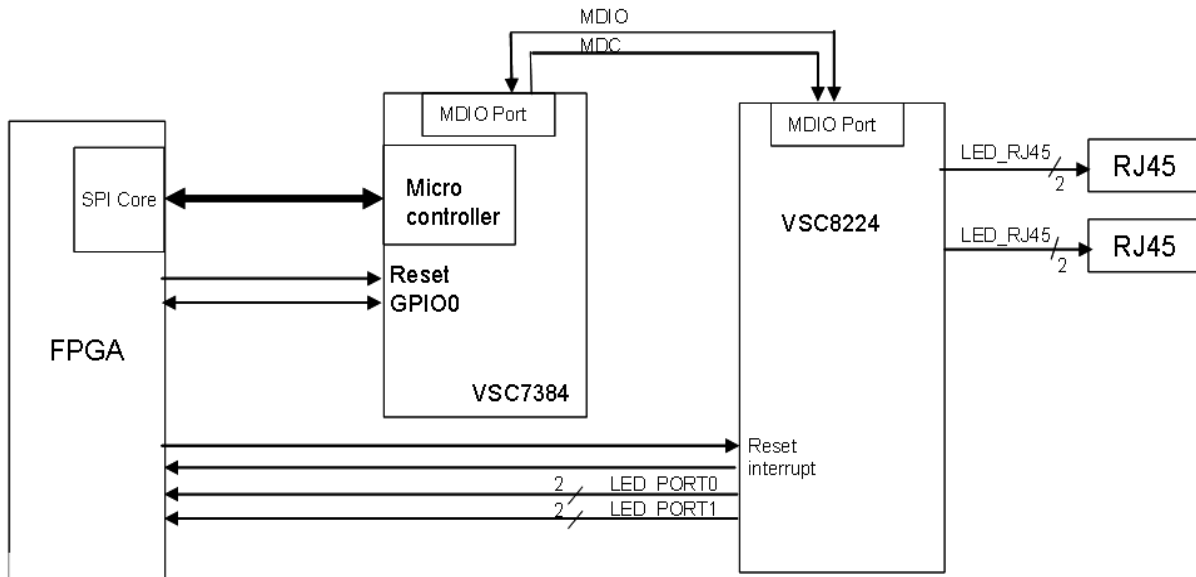


Figure 3-6. Ethernet Configuration

Table 3-3 summarizes the Ethernet switch port mappings.

Table 3-3. VSC7384 Port Mapping

VSC7384 Port	Interconnect Interface	Target
0	RGMII (full duplex, Gigabit mode)	DSP1 (GE1)
1	RGMII (full duplex, Gigabit mode)	DSP1 (GE2)

Table 3-3. VSC7384 Port Mapping (continued)

VSC7384 Port	Interconnect Interface	Target
2	RGMI (full duplex, Gigabit mode)	DSP2 (GE1)
3	RGMI (full duplex, Gigabit mode)	DSP2 (GE2)
4	RGMI (full duplex, Gigabit mode)	DSP3 (GE1)
5	RGMI (full duplex, Gigabit mode)	DSP3 (GE2)
6	RGMI (full duplex, Gigabit mode)	VSC8224 Transceiver [Port 0]
7	RGMI (full duplex, Gigabit mode)	VSC8224 Transceiver [Port 1]
8	RGMI (full duplex, Gigabit mode)	VSC8224 Transceiver [Port 2]
9	RGMI (full duplex, Gigabit mode)	VSC8224 Transceiver [Port 3]
10	Not used	—
11	Not used	—

For debug and analysis, the Ethernet switch registers can be accessed through the Ethernet switch UART. The terminal should be set to 115200 data rate, 8 data bits, and no parity, with echo-typed lines locally set to ON. The complete list of registers is available in the VSC7384 data sheet. An example of some useful register accesses is detailed in [Table 3-4](#).

Table 3-4. Ethernet Switch Register Accesses

Terminal Input	Register Access	Description
r 1 2 0	Read block 1, port 2, register 0x0	Read port 2 MAC configuration register
r 1 3 0	Read block 1, port 3, register 0x0	Read port 3 MAC configuration register
r 1 5 0x50	Read block 1, port 5, register 0x50	Read port 5 received octets
r 1 5 0x51	Read block 1, port 5, register 0x51	Read port 5 transmitted octets
w 1 5 0 0x302F0141	Write block 1, port 5, register 0x0	Write to MAC configuration register

3.4.2 RGMII Clock Delay

The RGMII specification requires the signal clock to be delayed by 1.5–2 ns at the receiving end of the data path. This clock delay can be added externally (extending clock trace length) or by using internal delays built into the device. The MSC8156 tap value can be selected through the GCR4 register.

The default GCR4 value, which is initially set in ROM code, differs between MSC8156 Rev1 silicon (used in Prototype MSC8156 AMC) and MSC8156 Rev2 silicon (used in Pilot MSC8156 AMC).

The GE1 track lengths differ on the AMC base card versions to accommodate boot over Ethernet, which uses the default GCR4.

NOTE

DSP2 GE1 has been changed to accommodate both MSC8156 and QoreIQ mezzanines.

Table 3-5. MSC8156 RGMII Delay (Prototype Build)

MSC8156	MSC8156 Prototype [Rev 1 MSC8156]		MSC8156 Pilot [Rev 2 MSC8156]	
	RX Clock Delay (ns)	TX Clock Delay (ns)	RX Clock Delay (ns)	TX Clock Delay (ns)
DSP1 GE1	1.6	1.6	0	0
DSP1 GE2	1.6	1.6	0	0
DSP2 GE1	1.6	1.6	0	0
DSP2 GE2	0	0	0	0
DSP3 GE1	1.6	1.6	0	0
DSP3 GE2	0	0	0	0

3.4.3 Ethernet Transceiver Configuration

On power up, the VSC8224 Ethernet transceiver is configured through eight CMODE configuration pins. These configure a subset of the MII registers within the device. The register block is then programmed through the management interface, which connects to the Ethernet switch. [Table 3-6](#) describes the CMODE configuration settings.

Table 3-6. CMODE Configuration Settings

Name	Value	Description
MAC Interface	000	RGMII with AutoCAT5/serial media sense
PHY Address [4:2]	100	Address = b100xx b10000 = Port 0 b10001 = Port 1 b10010 = Port 2 b10011 = Port 3
ActiPHY	0	Disable power management
LED4[1:0] LED3[1:0] LED2[1:0] LED1[1:0] LED0[1:0]	00 (not used) 00 (not used) 10 00 (not used) 00	LED0 = Link1000/activity LED2 = Link activity
LED pulse stretch/blink	0	Collision, activity, RX, and TX outputs will blink when active
LED combine link with activity	1	Indicates link only activity (LED2)
LED combine 10/100/1000 with activity	0	Indicate activity only (LED0)
LED combine collision with duplex	1	Indicate duplex condition [not used]
Speed/duplex auto negotiation advertisement [1:0]	01	10/100/1000Base-T, FDX, 10/100Base-T, HDX, 1000Base-X, FDX

Table 3-6. CMODE Configuration Settings (continued)

Name	Value	Description
Link speed down shift	1	Enable link speed downshift capability on two-pair cable or after three failed auto-negotiation attempts
Pause control[1:0]	11	Advertise 100Base TX
Remote fault control [1:0]	00	00 (not used)
SIGDET[3:0]	0	Pin is an input
RGMII Clock Skew[1:0]	00	No skew

The RJ45 LEDs have been configured to be on for link and blink for activity.

3.5 I²C Interface

The I²C bus connects the three DSPs, FPGA, and the SRIO switch together, and provides a method for bootstrap and communication, as shown in [Figure 3-7](#). Two EEPROMs (M24512-WMW6T) are provided on the bus: one for the DSPs and the other for the SRIO switch. The DSP EEPROM is at address 0x50, and the DSPs access 0x50 during boot, while the SRIO switch access 0x52 during boot. The SRIO switch can act as master or slave on the bus and is accessed at address 0x42.

Table 3-7. I²C Addresses

I ² C Address	Description
0x50	DSP EEPROM
0x52	SRIO switch EEPROM
0x42	SRIO switch

A voltage level shifter is used to translate from the 2.5-V DSP IO voltage to the FPGA/CPS10Q 3.3-V IO voltage.

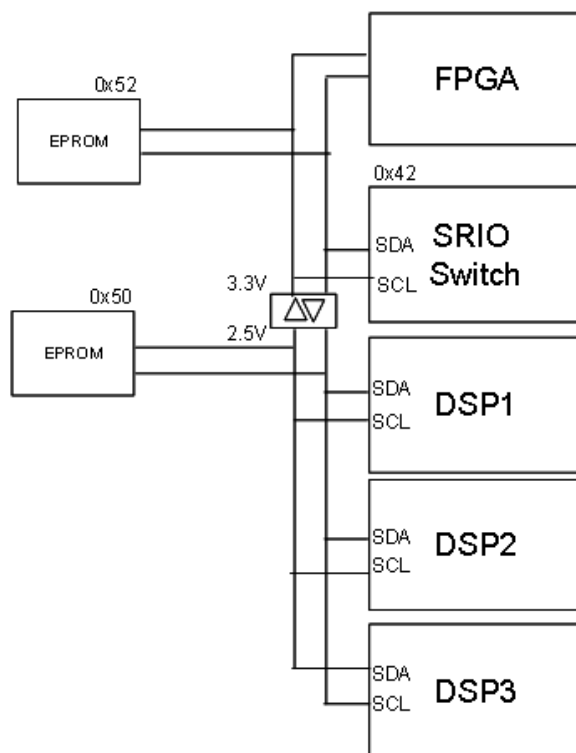


Figure 3-7. I²C Bus

The two EEPROM slaves are accessed through a DSP master for programming purposes. When programming the EEPROMs, the I²C bus is configured as a single bus through switch SW1.3. During normal MSC8156 AMC operation, the I²C bus is configured as two separate buses through SW1.3, enabling both the DSPs and the SRIO switch to act as master and access the bus at the same time. The SW1.3 switch connects to the voltage transceiver through the FPGA to enable or disable it.

3.6 SPI

The MSC8156 SPI allows the exchange of data with other devices containing an SPI. The MSC8156 AMC has 16 Mbyte of flash (Spansion S25FL128P) located on the AMC base card. The DSPs access this flash memory through the SPI bus, which routes through the FPGA. This memory gives the option to boot stand-alone with stored application code.

The SPI bus has been routed through the FPGA enabling it to utilize the MSC8156 SPIO pins as GPIO if the SPI option is not used.

Note that the SPI is intended for future use, and by default, it is not implemented in the FPGA.

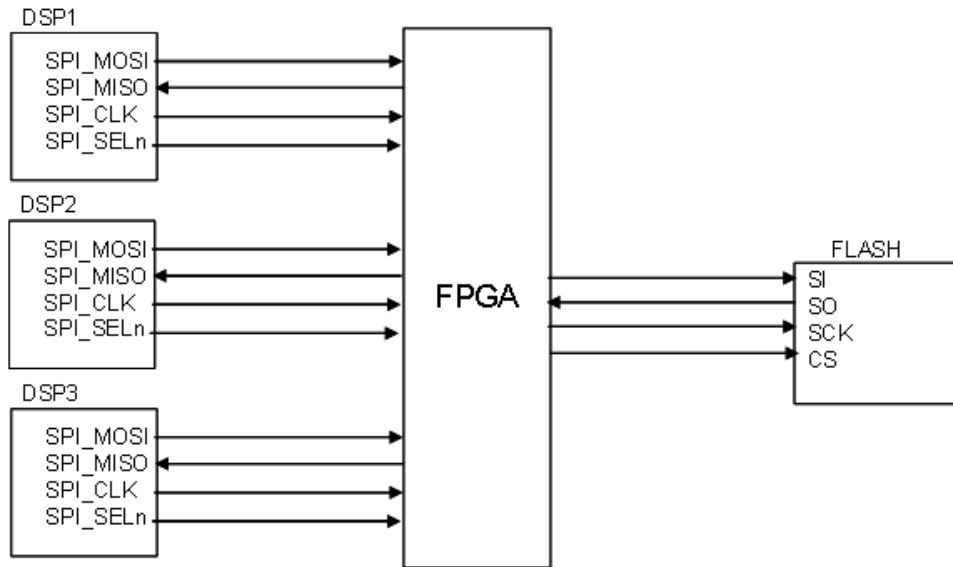


Figure 3-8. SPI

3.7 UART Interface

The three DSP UARTs and the Ethernet switch UART are multiplexed in the FPGA and routed to a mini type B USB connector on the front panel. An FTDI FT2232 transceiver carries out the UART to USB conversion. An LED indicates TX or RX activity at the interface. Virtual COM port (VCP) drivers enable the USB device to appear as an additional COM port available to the PC.

The driver is available from FTDI at <http://www.ftdichip.com/Drivers/VCP.htm>.

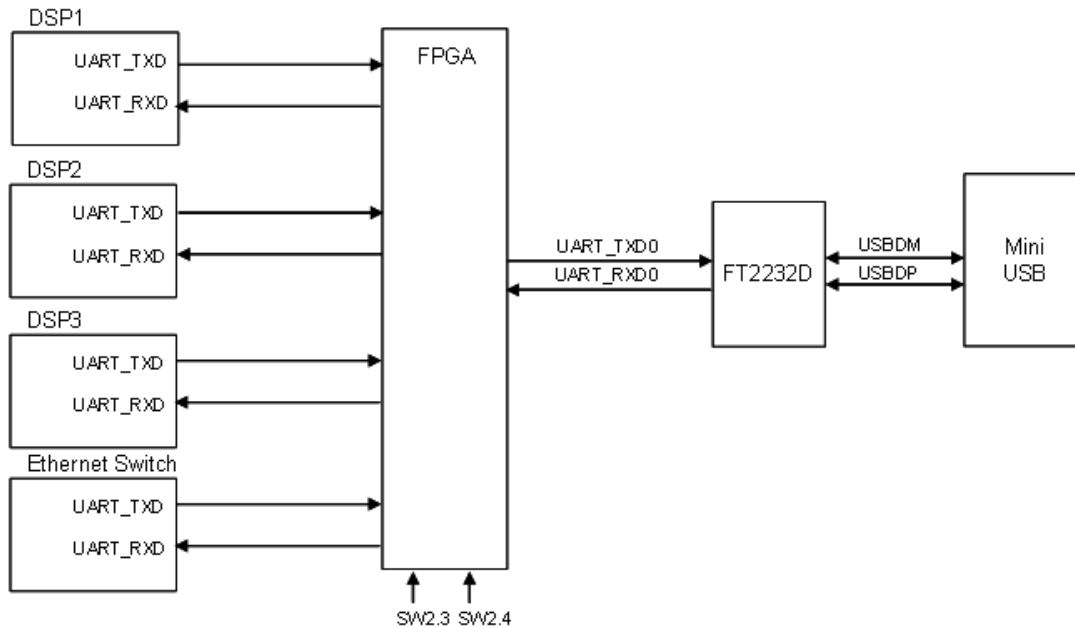


Figure 3-9. MSC8156 AMC UART to USB Interfaces

3.8 USB Host Interface

An integrated RJ45/USB type A connector provides a host USB interface for QorIQ AMC development. This is not used in the MSC8156 AMC.

3.9 System FPGA

The lattice LFXP2-8E-5FTN256C FPGA provides the following functions:

- Controls reset sequence of MSC8156 AMC components
- Drives the MSC8156 control and configuration signals
- Configures Ethernet switch through SPI
- Collects and distributes the GPIO or interrupts on the board
- MSC8156 JTAG control
- Multiplexes UARTs to the UART or USB transceiver
- Collects DIP switch inputs for board control
- Controls LED operation

3.9.1 FPGA SPI Master Interface

The Ethernet switch has an embedded core to control switch operation. The software image for the core is downloaded to the switch from the FPGA over an SPI, with the FPGA being the SPI host. The FPGA has an 8-Kbyte ROM that contains the program image.

A standard lattice USB to single-ended wire programming cable is used to program the FPGA through the programming header, which is located on the expansion card.

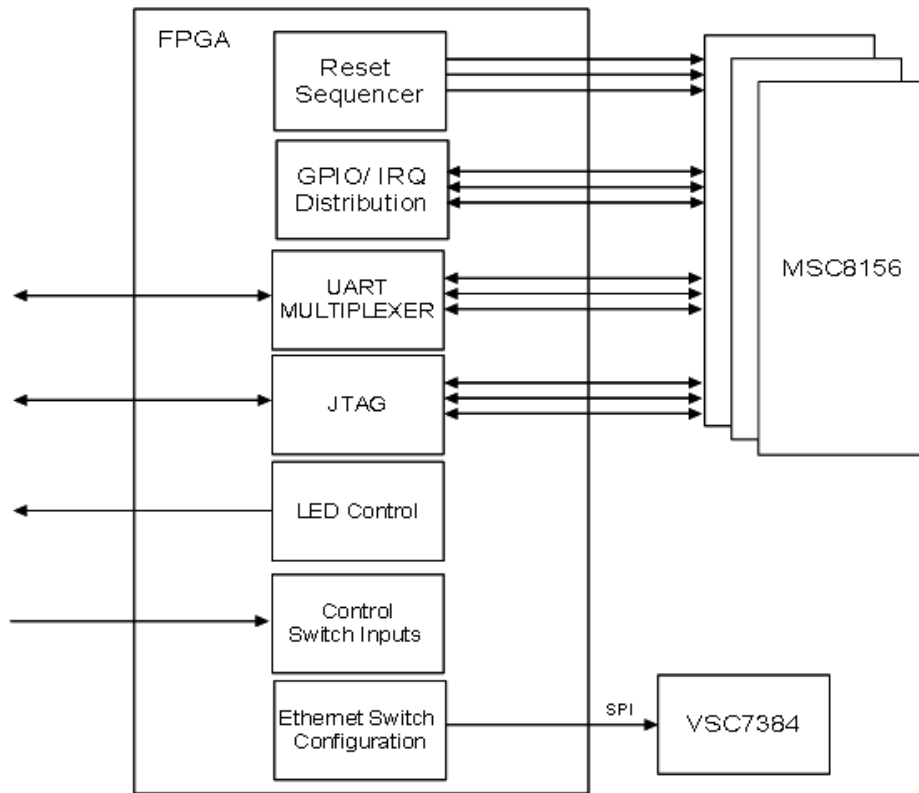


Figure 3-10. FPGA Functions

3.10 Reset Operation and Configuration

The FPGA controls the reset sequencing and configuration of the DSPs, Ethernet switch, Ethernet PHY, and SRIO switch. The connectivity is shown in [Figure 3-11](#).

The reset sequence is described below:

1. On applying the 12-V payload power, the MMC runs through the power up sequence to bring up the voltage rails.
2. Once the voltage rails are up, the MMC sends START_RESET_SEQUENCE command to FPGA through its FPGA_COMM link.
3. The FPGA starts its reset sequencer.
4. Based on the reset configuration word source (RCW_SRC) selection from switch SW1.2, the FPGA drives the RCW_SRC pins.
5. The three MSC8156's PORESET and HRESET signals are released (the MSC8156 SRESET signal is not used and is pulled high).
 - a) If RCW_SRC = Hard Code Option 1, each DSP configures itself independently with the same fixed reset configuration word (RCW) register settings, as described in [Section 3.10.1, "RCW from Hard Coded Option 1."](#)

- b) If RCW_SRC = I²C, Boot Port = SRIO, each DSP receives its RCW register settings from the EEPROM through the I²C bus, as described in [Section 3.10.2, “Loading RCW from External I2C.”](#)
- 6. The Ethernet switch and PHY resets are released.
- 7. The SRIO switch reset is released.
- 8. The switch initializes itself from its boot EEPROM at address 0x52.
- 9. The FPGA then downloads the software image for the Ethernet switch core through its dedicated SPI.
 - a) Once download is complete, the FPGA applies a register reset to the Ethernet switch, which then configures itself from its core.
 - b) The switch configures the Ethernet PHY over the MDIO interface.
- 10. Reset sequence is complete and indicated by the LED D5 heartbeat.
- 11. The platform is now ready for boot over SRIO or general tools access.

3.10.1 RCW from Hard Coded Option 1

When the MSC8156 is configured to load the hard coded RCW, it configures itself with the default values described in [Table 3-8](#) and [Table 3-9](#).

Table 3-8. RCWLR (Hard Coded)

RCWLR bit	Name	Value	Description
[31:30]	CLKO	00	Source is PLL0 [CLKOUT = 80 MHz]
29	—	0	Reserved
28:24	S1P	01010	SerDes port 1, PCIe 1x SGMII1. SGMII2
23:20	S2P	0011	SerDes port 0, RapidIO 4x 3.125 GHz
19:18	0	00	Reserved
17	SCLK2	1	SerDes ref clock = 125 MHz
16	SCLK1	1	SerDes ref clock = 125 MHz
15:6	—	0000000000	Reserved
5:0	MODCK	000000	Clock mode 0
DSP1: RCWLR = 0x0A330000 DSP2: RCWLR = 0x0A330000 DSP3: RCWLR = 0x0A330000			

Table 3-9. RCWHR (Hard Coded)

RCW Bit High	Name	Value	Description
31:30	—	00	Reserved
29	EWDT	0	Disable watch dog timer
28	PRDY	0	PCI express not ready
27:24	BPRT	0000	Boot port is SRIO (BPRT value ignored)
23	RIO	1	Host access after boot, enabled
22	RPT	0	RIO pass through disabled
21	RHE	0	RapidIO controller is host
20:19	—	00	Reserved
18	RM	0	Not reset master
17:13	—	00000	Reserved
12	GE1	1	RGMII selected
11	GE2	1	RGMII selected
10	R1A	0	SRIO0 does not accept all device IDs
9	R2A	0	SRIO1 does not accept all device IDs
8:3	Device ID	000000	Device ID = 0
2	—	0	Reserved
1	RMU	0	Access local memory port 0
0	CTLS	1	Common transport type is a large system
DSP1: RCWHR = 0x00801801 DSP2: RCWHR = 0x00801801 DSP3: RCWHR = 0x00801801			

3.10.2 Loading RCW from External I²C

When loading the RCW from external I²C, the DSPs receive their configuration data from an external I²C EEPROM at address 0x50.

The FPGA configures DSP1 as the DSP master by asserting STOP_BS = 0, and DSP2 and DSP3 as slave devices by asserting STOP_BS = 1. The DSPs receive their RCW data in the following three stages:

1. DSP1 reads its RCW from I²C EEPROM while holding the two slave DSPs off the I²C bus. To do this, DSP1 uses its GPIO0 and GPIO1 pins to control the STOP_BS pins of the slave DSPs.
2. DSP1 reads the RCW for the two slave devices. It then configures its own I²C controller to emulate an EEPROM at address 0x57.

- DSP1 releases DSP2's STOP_BS pin. The released slave then reads its RCW data from I²C address 0x57 (DSP1). Once this has completed, it releases DSP3 that also reads its RCW from I²C address 0x57 (DSP1).

Table 3-10 and Table 3-11 describe the RCW data that is stored in the EEPROM. These values represent the default values and can be changed through the CodeWarrior SDOS EEPROM burner utility, if required.

Table 3-10. RCWLR (Load from I²C)

RCWLR Bit	Name	Value	Description
[31:30]	CLKO	01	Source is PLL1 [CLKOUT = 100 MHz]
29	—	0	Reserved
28:24	S2P	00011	SerDes Port 0: RapidIO 4x 3.125 GHz
23:20	S1P	0011	SerDes Port 1: RapidIO 4x 3.125 GHz
19:18	—	00	Reserved
17	SCLK2	1	SerDes reference clock = 125 MHz
16	SCLK1	1	SerDes reference clock = 125 MHz
15:8	—	0	Reserved
7	PLL1DIS	0	PLL1 enabled (required for clock mode 0)
6	—	-	Reserved
5:0	MODCK	000000	Clock mode 0
DSP1: RCWLR = 0x43330000 DSP2: RCWLR = 0x43330000 DSP3: RCWLR = 0x43330000			

Table 3-11. RCWHR (Load from I²C)

RCW Bit High	Name	Value	Description
31:30	RES	00	Reserved
29	EWDT	0	Disable watch dog timer
28	PRDY	0	PCI express not ready
27:24	BPRT	0001	Boot port = SRIO no I ² C
23	RIO	1	Host access after boot, enabled
22	RPT	0	RIO pass through disabled
21	RHE	0	RapidIO controller is agent
20:19	—	00	Reserved
18	RM	1 0 0	DSP1 = Reset master DSP2 = Reset slave DSP3 = Reset slave
17:13	—	00000	Reserved
12	GE1	1	RGMII selected

Table 3-11. RCWHR (Load from I²C) (continued)

11	GE2	1	RGMII selected
10	R1A	0	Do not accept all device IDs
9	R2A	0	Do not accept all device IDs
8:3	Device ID	000000 000001 000010	DSP1 = 000000 DSP2 = 000001 DSP3 = 000010
2	—	0	Reserved
1	RMU	0	Access local memory port 0
0	CTLS	1	Common transport type is a large system
DSP1: RCWHR = 0x01841801 DSP2: RCWHR = 0x01801809 DSP3: RCWHR = 0x01801811			

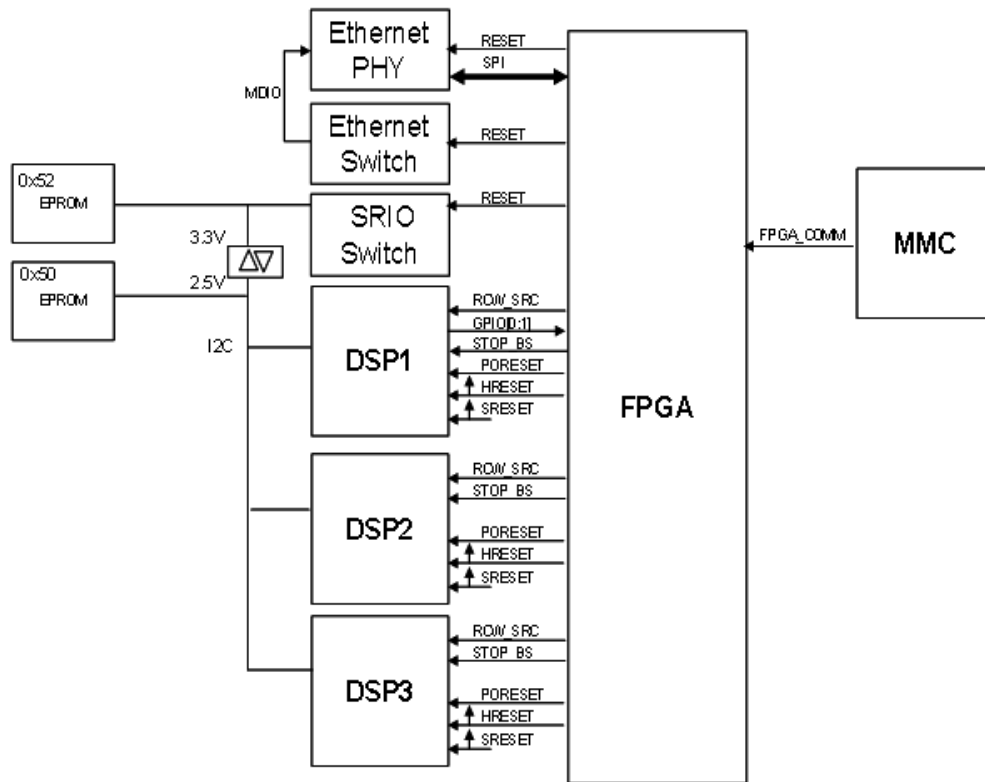


Figure 3-11. Reset and Configuration Control

3.11 GPIO/Timers and Interrupts

A number of GPIOs, timers, and interrupts are routed from the DSP, Ethernet, and SRIO blocks to the FPGA. These can be configured in the FPGA, as required. Note that some of these signals are multiplexed with the reset configuration signals. Once the reset is complete, the signals revert to the GPIO, timer, or interrupt option.

Table 3-12. GPIO/Timer and IRQ Signals Connected to FPGA

Signal	Comment
Each MSC8156	
GPIO0/IRQ0	Used for I ² C boot control
GPIO1/IRQ1	Used for I ² C boot control
GPIO17	Multiplexed with SPI_SCK
GPIO18	Multiplexed with SPI_MOSI
GPIO19	Multiplexed with SPI_MISO
GPIO20	Multiplexed with SPI_SL
GPIO24/TMR1	Multiplexed with RCW_SRC2
GPIO25/TMR2	Multiplexed with RCW_SRC1
GPIO27/TMR4	Multiplexed with RCW_SRC0
GPIO28	Multiplexed with UART_RXD
GPIO29	Multiplexed with UART_TXD
GPIO30	Multiplexed with I ² C_SCL
GPIO31	Multiplexed with I ² C_SDA
INT_OUT	Nonmaskable interrupt
NMI	Nonmaskable interrupt
SRIO Switch	
IRQ	—
Ethernet Switch	
GPIO0	—
Ethernet Transceiver	
IRQ	—

3.12 Mezzanine Board Identification Pins

Three board identification signals BRD_ID[2:0] are used to identify the type of mezzanine located on the AMC base card. These signals are connected to the FPGA to identify the appropriate reset and control flow. The MSC8156 Mezzanine has ID 3b001.

3.13 AMC Connector

The backplane edge connector provides connectivity to conductive traces on both sides of the AMC PCB. There are 170 traces in total. The connector interfaces the following:

- Four 4x SerDes (16 wire)
- Two SGMII Ethernet interfaces

Functional Description

- AMC fabric clocks
- AMC telecom clocks (TCLKA,TCLKB,TCLKC, and TCLKD)
- AMC JTAG

The card is mechanically designed to fit into an AMC slot through this connector. The connector is hard gold plated for improved insertion durability.

This connector pin out is described in [Table 3-13](#).

Table 3-13. AMC Connector Signal Pin Definitions

Pin #	AMC Definition	Specific Signal Description	Pin #	AMC Definition	Specific Signal Description
01	GND	—	170	GND	—
02	+12 V	—	169	TDI	AMC_TDI
03	PS1#	PS1_N	168	TDO	AMC_TDO
04	MP	IPMCV	167	TRST#	AMC_TRST
05	GA0	GA0	166	TMS	AMC_TMS
06	RSRVD	n/c	165	TCLK	AMC_TCLK
07	GND	—	164	GND	—
08	RSRVD	n/c	163	TX20+	AMC_SRIO3_TXD_P3
09	+12 V	—	162	TX20–	AMC_SRIO3_TXD_N3
10	GND	—	161	GND	—
11	TX0+	AMC_TXD_P0_P	160	RX20+	AMC_SRIO3_RXD_P3
12	TX0–	AMC_TXD_P0_N	159	RX20–	AMC_SRIO3_RXD_N3
13	GND	—	158	GND	—
14	RX0+	AMC_RXD_P0_P	157	TX19+	AMC_SRIO3_TXD_P2
15	RX0–	AMC_RXD_P0_N	156	TX19–	AMC_SRIO3_TXD_N2
16	GND	—	155	GND	—
17	GA1	GA1	154	RX19+	AMC_SRIO3_RXD_P2
18	+12 V	—	155	RX19–	AMC_SRIO3_RXD_N2
19	GND	—	152	GND	—
20	TX1+	AMC_TXD_P0_P	151	TX18+	AMC_SRIO3_TXD_P1
21	TX1–	AMC_TXD_P0_N	150	TX18–	AMC_SRIO3_TXD_N1
22	GND	—	149	GND	—
23	RX1+	AMC_RXD_P0_P	151	RX18+	AMC_SRIO3_RXD_P1
24	RX1–	AMC_RXD_P0_N	150	RX18–	AMC_SRIO3_RXD_N1
25	GND	—	146	GND	—
26	GA2	GA2	145	TX17+	AMC_SRIO3_TXD_P0

Table 3-13. AMC Connector Signal Pin Definitions (continued)

27	+12 V	—	144	TX17–	AMC_SRIO3_TXD_N0
28	GND	—	143	GND	—
29	TX2+	n/c	142	RX17+	AMC_SRIO3_RXD_P0
30	TX2–	n/c	141	RX17–	AMC_SRIO3_RXD_N0
31	GND	—	140	GND	—
32	RX2+	n/c	139	TCLKD+	AMC_CLKD_P
33	RX2–	n/c	138	TCLKD–	AMC_CLKD_N
34	GND	—	137	GND	—
35	TX3+	n/c	136	TCLKC+	AMC_CLKC_P
36	TX3–	n/c	135	TCLKC–	AMC_CLKC_N
37	GND	—	134	GND	—
38	RX3+	n/c	133	TX15+	AMC_SRIO2_TXD_P3
39	RX3–	n/c	132	TX15–	AMC_SRIO2_TXD_N3
40	GND	—	131	GND	—
41	ENABLE #	ENABLE_N	130	RX15+	AMC_SRIO2_RXD_P3
42	+12 V	—	129	RX15–	AMC_SRIO2_RXD_N3
43	GND	—	128	GND	—
44	TX4+	AMC_SRIO0_TXD_P0	127	TX14+	AMC_SRIO2_TXD_P2
45	TX4–	AMC_SRIO0_TXD_N0	126	TX14–	AMC_SRIO2_TXD_N2
46	GND	—	125	GND	—
47	RX4+	AMC_SRIO0_RXD_P0	124	RX14+	AMC_SRIO2_RXD_P2
48	RX4–	AMC_SRIO0_RXD_N0	123	RX14–	AMC_SRIO2_RXD_N2
49	GND	—	122	GND	—
50	TX5+	AMC_SRIO0_TXD_P1	121	TX13+	AMC_SRIO2_TXD_P1
51	TX5–	AMC_SRIO0_TXD_N1	120	TX13–	AMC_SRIO2_TXD_N1
52	GND	—	119	GND	—
53	RX5+	AMC_SRIO0_RXD_P1	118	RX13+	AMC_SRIO2_RXD_P1
54	RX5–	AMC_SRIO0_RXD_N1	119	RX13–	AMC_SRIO2_RXD_N1
55	GND	—	116	GND	—
56	SCL_L	AMC_SCL	115	TX12+	AMC_SRIO2_TXD_P0
57	+12 V	—	114	TX12–	AMC_SRIO2_TXD_N0
58	GND	—	113	GND	—
59	TX6+	AMC_SRIO0_TXD_P2	112	RX12+	AMC_SRIO2_RXD_P0
60	TX6–	AMC_SRIO0_TXD_N2	111	RX12–	AMC_SRIO2_RXD_N0

Table 3-13. AMC Connector Signal Pin Definitions (continued)

61	GND	—	110	GND	—
62	RX6+	AMC_SRIO0_RXD_P2	109	TX11+	AMC_SRIO1_TXD_P3
63	RX6-	AMC_SRIO0_RXD_N2	108	TX11-	AMC_SRIO1_TXD_N3
64	GND	—	107	GND	—
65	TX7+	AMC_SRIO0_TXD_P3	106	RX11+	AMC_SRIO1_RXD_P3
66	TX7-	AMC_SRIO0_TXD_N3	105	RX11-	AMC_SRIO1_RXD_N3
67	GND	—	104	GND	—
68	RX7+	AMC_SRIO0_RXD_P3	103	TX10+	AMC_SRIO1_TXD_P2
69	RX7-	AMC_SRIO0_RXD_N3	102	TX10-	AMC_SRIO1_TXD_N2
70	GND	—	101	GND	—
71	SDA_L	AMC_SDA	100	RX10+	AMC_SRIO1_RXD_P2
72	+12 V	—	99	RX10-	AMC_SRIO1_RXD_N2
73	GND	—	98	GND	—
74	CLKA+	AMC_CLKA_P	97	TX9+	AMC_SRIO1_TXD_P1
75	CLKA-	AMC_CLKA_N	96	TX9-	AMC_SRIO1_TXD_N1
76	GND	—	95	GND	—
77	CLKB+	AMC_CLKB_P	94	RX9+	AMC_SRIO1_RXD_P1
78	CLKB-	AMC_CLKB_N	93	RX9-	AMC_SRIO1_RXD_N1
79	GND	—	92	GND	—
80	FCLKA+	AMC_FCLK_P	91	TX8+	AMC_SRIO1_TXD_P0
81	FCLKA-	AMC_FCLK_N	92	TX8-	AMC_SRIO1_TXD_N0
82	GND	—	89	GND	—
83	PS0#	PS0_N	88	RX8+	AMC_SRIO1_RXD_P0
84	+12 V	—	87	RX8-	AMC_SRIO1_RXD_N0
85	GND	—	86	GND	—

3.13.1 AMC Backplane JTAG

The backplane JTAG is routed direct to the FPGA for future development work.

3.13.2 AMC Backplane Telecom Clocks

The four AMC backplane telecom clocks TCLKA, TCLKB, TCLKC, and TCLKD are connected to the FPGA in emulated mode. This mode uses external biasing resistors, as shown in [Figure 3-12](#). Use of these clocks is application dependent, and the clocks can be routed through the FPGA as required.

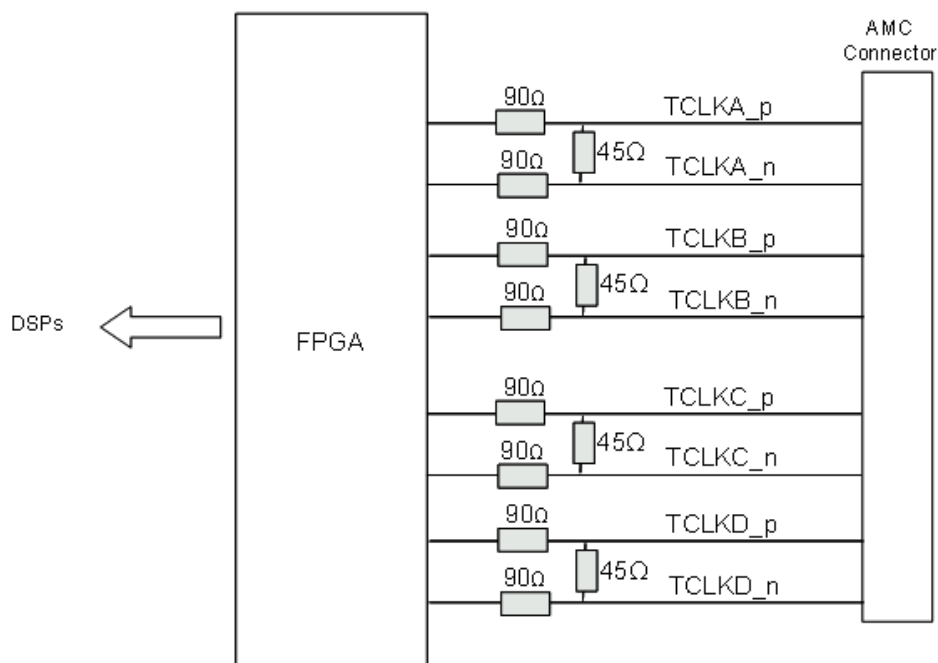


Figure 3-12. Telecom Clocks

3.14 Power Supply System

3.14.1 Power Options

There are two possible power options for the card depending on the working mode.

- Standard AMC mode
 - 12 V supplying 60-W payload power through the AMC connector
 - 3.3 V supplying 150 mA for board management through the AMC connector
- Stand-alone mode
 - 12 V supplying 60-W payload power through the optional barrel connector
 - On-board DC–DC converter generating the 3.3-V management power from the 12-V input. This converter is controlled through the SW1.7 switch.

Freescale recommends running the MSC8156 AMC in standard AMC mode in an xTCA chassis to provide the correct power and cooling.

3.14.2 Power Supplies

The required voltages for the card are generated locally on-board from the 12-V supply using DC–DC converters, as shown in [Figure 3-13](#).

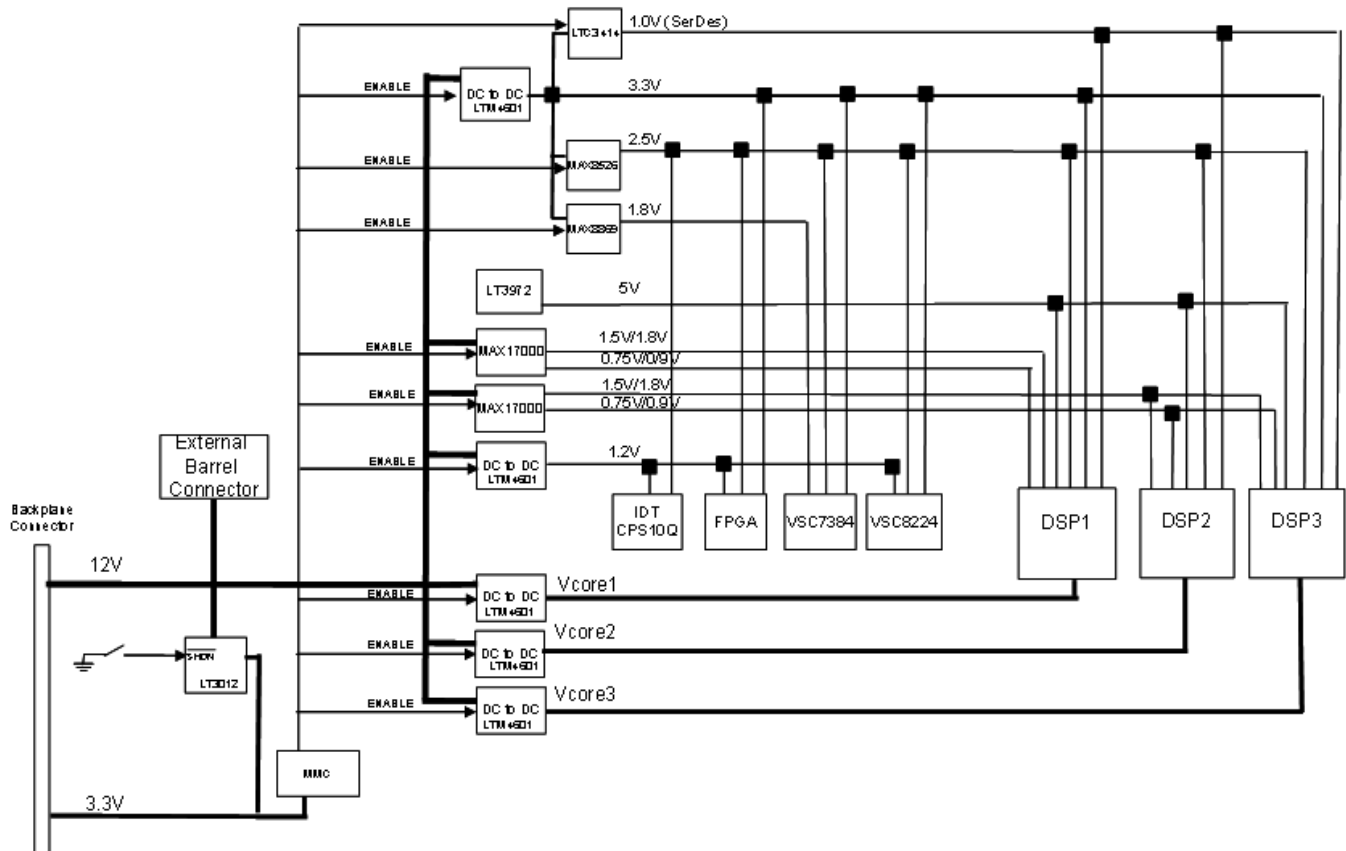


Figure 3-13. Power Architecture

Three linear LTM4601 power modules are used to supply core power to the three DSPs. This voltage can be adjusted through resistor changes to select between 0.8 V and 1.2 V. By default, the core voltages are set to 1.0 V.

In addition, the voltage can be controlled from the MMC through the margining pins of the LTM4601 modules. This enables MMC firmware updates to change the voltage.

The margining offset has been set to $\pm 5\%$ of V_{out} through the LTM4601's MPGM pin, as described in Table 3-14.

Table 3-14. VCORE Margining

MARG0	MARG1	MODE	V_{OUT} (V)
0	0	No margin	1.0 (default)
0	1	Margin up	1.05
1	0	Margin down	0.95
1	1	No margin	1.0

The option exists to parallel up the three LTM4601s to create a single voltage generator greater than 30 A. In this scenario, the Vcore1 module acts as the master core, which synchronizes with the two slave LTM4601s for a combined output.

Table 3-15 describes the configuration changes required on the board. By default, the MSC8156 AMC is configured to operate separate core supplies.

Table 3-15. Single Voltage Generator Modifications

Component	Separate Core Supplies (Default)	Single Core Supply
R_1 (R279)	90.9 K	Replace with 30.1 K KOA RK73H1ETTP3012F
R_2 (R290)	90.9 K	Replace with 100 pf Kemet C0402C101J4GAC
R_3 (R189)	90.9 K	Replace with 100 pf Kemet C0402C101J4GAC
R_5 (R283)	0 Ω	DNP
R_6 (R287)	0 Ω	DNP
R_7 (R286)	0 Ω	DNP
R_8 (R281)	0 Ω	DNP
R_10 (R194)	0 Ω	DNP
R_11 (R191)	0 Ω	DNP
R_12 (R192)	0 Ω	DNP
R_13 (R195)	0 Ω	DNP
R_14 (R298)	DNP	0 Ω
R_15 (R296)	DNP	0 Ω
R_16 (R74)	DNP	0 Ω
R_17 (R185)	DNP	0 Ω
R_18 (R285)	DNP	0 Ω
R_19 (R206)	DNP	0 Ω
R_20 (R193)	DNP	0 Ω
R_21 (R284)	DNP	0 Ω
R_22 (R278)	DNP	0 Ω
R_23 (R277)	DNP	0 Ω
LK1	DNP	Populate
LK4	DNP	Populate

An LTC3414 DC–DC converter generates a separate 1.0 V for the SerDes voltage. This voltage can be adjusted through resistor changes to select between 0.8 V and 1.2 V. By default, the voltage is set to 1.0_V. The option exists to connect the SerDes voltage direct to the core voltage through LK2, 3, and 5 links. By default, these links are not populated, and board runs with separate SerDes and core voltages.

The DDR3 voltages (1.5 V/0.75 V) are generated from two power circuits. One circuit generates the voltage for DSP1 and the second for a combination of DSP2 and DSP3. Both circuits can generate DDR2 voltages (1.8 V/0.9 V). The DDR voltage has been split to enable future mezzanines to have a combination of DDR2 and/or DDR3. The MMC drives a signal to the circuitry to select the DDR2 or DDR3 option.

3.14.3 Power Sequence

The board power up sequence is initiated by the MMC that controls the timing of the enable signals to the various DC–DC converters. The power up sequence restrictions are described in [Table 3-16](#).

Table 3-16. Power Sequencing Requirements

Device	Notes	Sequence
MSC8156	Core voltage first then IO in any order	1V0 then 2V5
FPGA	No specific power up options Internal power good signal generated from VCC (1V2) and VCCAUX (3V3) pins, so ensure 2V5 is not last supply up	2V5/3.3V then 1V2
CPS10Q	No power sequence requirements	–
VSC7384	$VDD_OUT33 (3V3) \leq VDD_IO25 (2V5) + 1.35 V$ $VDD_PLL (2V5) \leq VDD_IO25 (2V5) + 0.5 V$	2V5 then 3V3
VSC8224	No power sequence requirements	–

To meet the above requirements, the following order is used:

$$VCORE1 \geq VCORE2 \geq VCORE3 \geq 1V0 \geq 1V8 \geq 2V5 \geq 3V3 \geq 1V2 \geq 1V5/0V75$$

3.15 MMC

The MMC provides the control of the AMC when operating in an xTCA chassis. It controls areas, such as carrier IPMC communications, power up and hot swap, temperature control, and FRU information.

The AMC base card uses the Pigeon-Point MMC solution based on the AVR microprocessor ATmega128. The device contains 128 Kbyte of Flash, 4 Kbyte of SRAM for runtime operation, and 2 Kbyte of EEPROM memory for storage of nonvolatile data.

A high-level overview of the MMC architecture is shown [Figure 3-14](#).

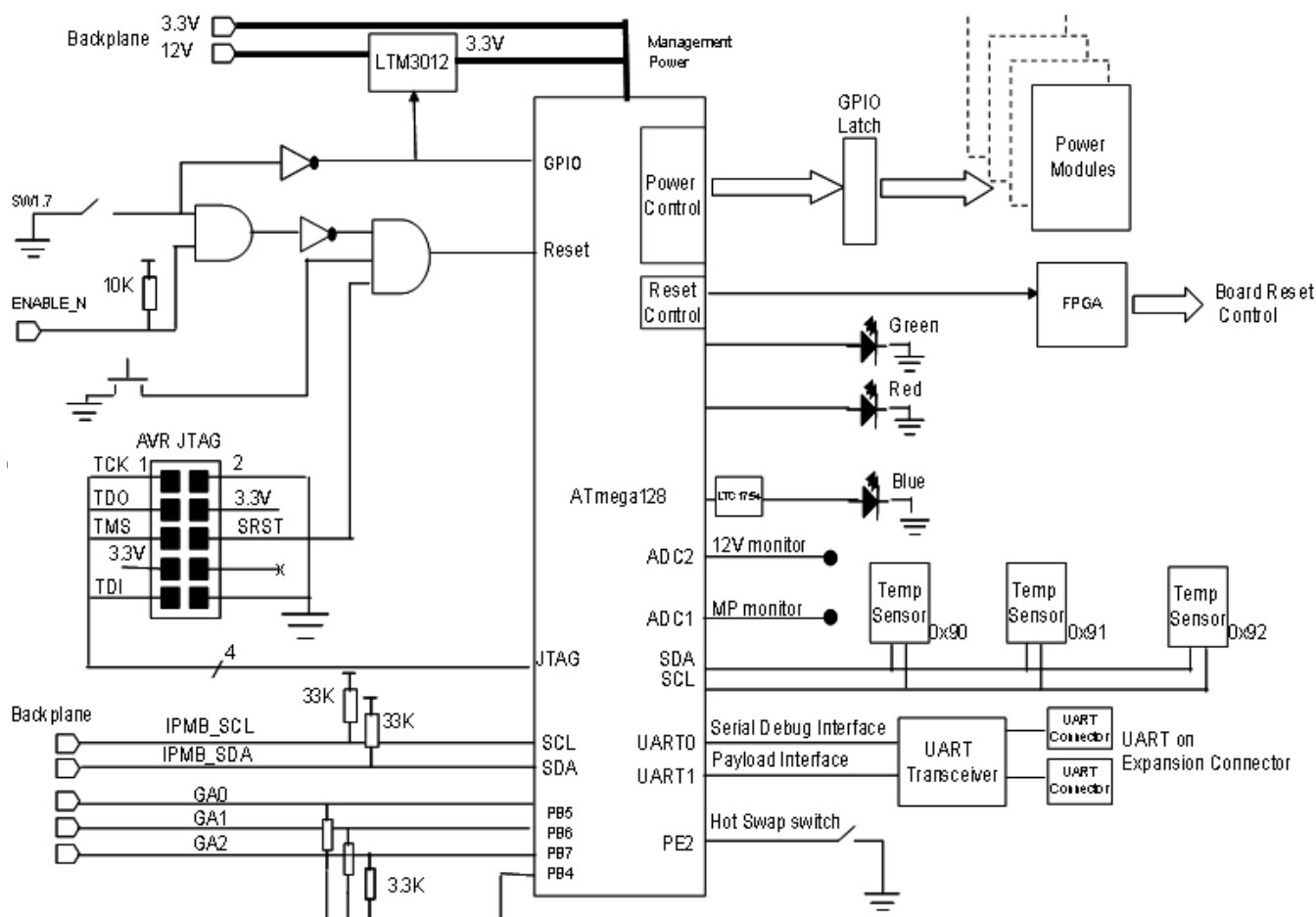


Figure 3-14. MMC

3.15.1 Reset

The reset pin of the AVR is connected to the backplane's enable signal through logical inverter. Both enable and reset are pulled up through 10 K Ω . The carrier IPMC drives this signal to control the MMC.

3.15.2 JTAG

A 10-pin JTAG connector compatible with the ATMEL AVR JTAG ICE tool enables to install firmware over the JTAG interface. The connector is located on the expansion card.

3.15.3 Serial Debug Interface (UART0)

The AVR uses UART0 as a serial debug interface (SDI) to output debug and diagnostic information. The UART0 interfaces to a 9-pin RS232 receptacle on the expansion card. The terminal should be set to 9800 8-N-1. A typical output will appear as follows:

```
<_>: BMR-AVR Firmware (v1.5.2), MMC edition.
<_>: Pigeon Point Systems (c) Copyright 2004-2007.
<_>: Reset type: hard, reset cause: external reset
```

Functional Description

```

<_>: E-keying link #00 is deactivated
<_>: E-keying link #01 is deactivated
<_>: E-keying link #02 is deactivated
<_>: E-keying link #03 is deactivated
<_>: Geographic address: UGU
<_>: IPMB address: 0x7A
  
```

3.15.4 Payload Interface (UART1)

The payload interface can be used for communication with the payload. The UART1 interfaces to a 9-pin RS232 receptacle on the expansion card. The terminal should be set to 9800 8-N-1.

3.15.5 Voltage Monitoring

The AVR monitors the 3.3-V management (IPMCV) and 12-V payload voltages. These are connected to the device's ADC1 and ADC2 pins.

3.15.6 IPMB

The AVR MMC provides an IPMB-L interface using the AVR's built-in controller. This connects to the AMC edge connector IPMB pins—SDA and SCL—enabling communication with the carrier IPMC resource. The signals are pulled up to IPMC through 3.3-K Ω resistors.

3.15.7 Geographical Address

The geographical address (chassis slot location) is implemented using four GPIO pins. The three pins are pulled up to GA_REF through 3.3-K Ω resistors.

3.15.8 Hot Swap Interface

The AVR provides a hot swap interface that comprises a hot swap handle and a blue hot swap LED.

The hot swap switch is activated by the module latching mechanism and is used to confirm insertion or indicate a request for an extraction to the MMC. This switch signal is pulled up to management power so that it can be read when payload power is not applied. The MMC sends an event to the carrier IPMC when the hot swap switch changes state.

The blue hot swap LED is mounted on the front of the face plate. It provides feedback on the hot swap state of the module. It has a number of different states—On, Off, and blink. Full details of the LED operation are described in the *PICMG AMC.0 R2.0 Advanced Mezzanine Card Base Specification*.

Table 3-17 summarizes a typical hot swap sequence.

Table 3-17. Hot Swap Sequence

Description	Hot Swap Handle	Hot Swap LED
AMC insertion and power up		
AMC inserted into chassis with handle open	Open	On

Table 3-17. Hot Swap Sequence (continued)

AMC handle closed (requests activation from chassis IPMI Controller)	Closed	Blinks
Activation granted and AMC powers up	Closed	Off
AMC removal		
AMC handle pulled open (requests de-activation from chassis IPMI controller)	Open	Blinks
Deactivation granted and AMC powers down (AMC can now be removed)	Open	On

3.15.9 MMC LEDs

Two GPIO-controlled LEDs provide additional FRU information. A red LED switches on when the FRU is in an out-of-service (OOS) state. A green LED indicates the in-service state (IS) and switches on when the device is operating normally.

3.15.10 Temperature Sensor

The AVR provides three temperature sensors, which are spaced on the mezzanine side of the board. Each of the sensors resides on the AVR's Master-only I²C bus, which is controlled through GPIO pins. The sensor addresses are set to 0x90, 0x91, and 0x92.

3.15.11 Power Control Through GPIO

The MMC controls the sequencing of the power modules through GPIO pins. These signals are fed through an SN74LVTH16373 latch to the DC modules and DC-DC converters.

3.15.12 MMC to FPGA Interface

A 2-bit interface MMC_FPGA_COM[1:2] connects the ATmega128 to the FPGA. The MMC drives the MMC_FPGA_COM1 signals to start the reset sequencer in the FPGA.

3.15.13 FRU Data

The FRU data stored in the MMC that contains MSC8156 AMC product and configuration information is described in [Appendix B, "FRU Data."](#)

3.15.14 Stand-Alone Mode

In stand-alone mode, the MMC powers up the board without the need for a chassis or an IPMI controller. SW1.7 is used to select this mode. The switch sets the backplane ENABLE signal and switches on the on-board 12 V to 3.3 V DC-DC converter, which generates the management power. In stand-alone mode, the SDI output appears as follows:

```
<_>: BMR-AVR Firmware (v1.5.2), MMC edition.
<_>: Pigeon Point Systems (c) Copyright 2004-2007.
<_>: Reset type: hard, reset cause: external reset
<_>: E-keying link #00 is deactivated
```

Functional Description

```

<_>: E-keying link #01 is deactivated
<_>: E-keying link #02 is deactivated
<_>: E-keying link #03 is deactivated
<_>: Geographic address: UUU
<_>: Invalid geographic address
Running Standalone
<_>: IPMB address: 0x6F
<L>: IPMB error: no acknowledge
<E>: event message delivery failed
  
```

3.16 Expansion Card

A number of programming headers and connectors are offloaded to an expansion card through the Hirose FH12S-30S-0.5SV connector due to the board density. These connectors are described in [Table 3-18](#).

Table 3-18. Connectors

Reference	Description	Part
P1	FPGA programming header	Header (Samtec TSM-105-01-TM-DV-P)
J3	COP JTAG header (QoreIQ)	Header (Samtec TSM-108-01-S-DV-P)
J2	AVR MMC programming	Header (Samtec TSM-105-01-S-DV-P-TR)
J4	MMC SDI UART	9-pin D-Type Female RS232
J5	MMC payload UART	9-pin D-Type Female RS232

Figure 3-15 shows the connector positioning and the connector pin outs.

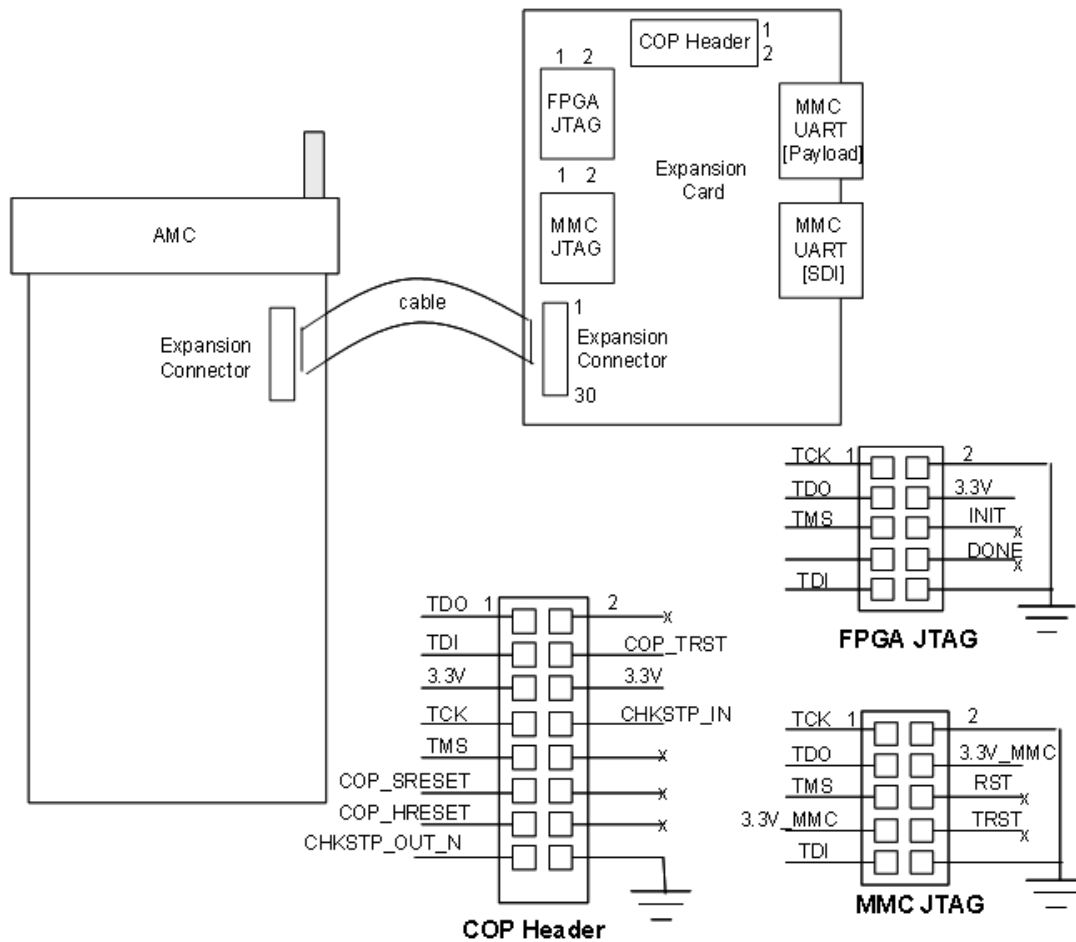


Figure 3-15. Expansion Card Connectors

3.17 Mechanicals

3.17.1 Layout

The board complies with the AMC full-height dimensions specified in *PICMG AMC.0 R2.0 "Advanced Mezzanine Card Base Specification."*

3.17.2 Heatsink

To accommodate different mezzanine options, each MSC8156 mezzanine has a dedicated heatsink. The heatsink is located through four holes on the MSC8156 Mezzanine, two of which also connect the mezzanine to the AMC base card through spacers, as shown in Figure 3-16. An additional small heatsink is placed on the CPS10Q SRIO switch. The heatsink layout is shown in Figure 3-17.

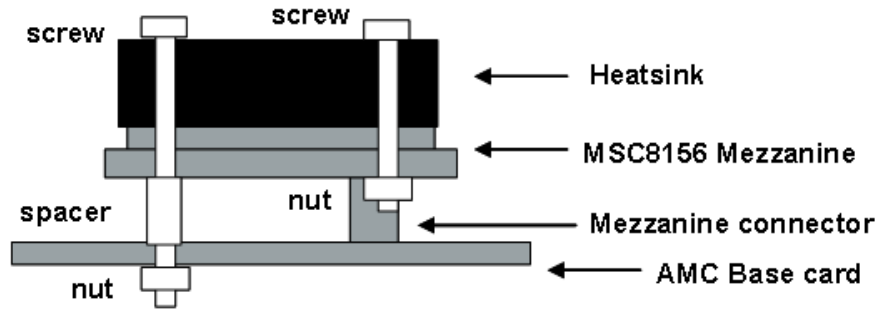


Figure 3-16. MSC8156 Mezzanine Heatsink

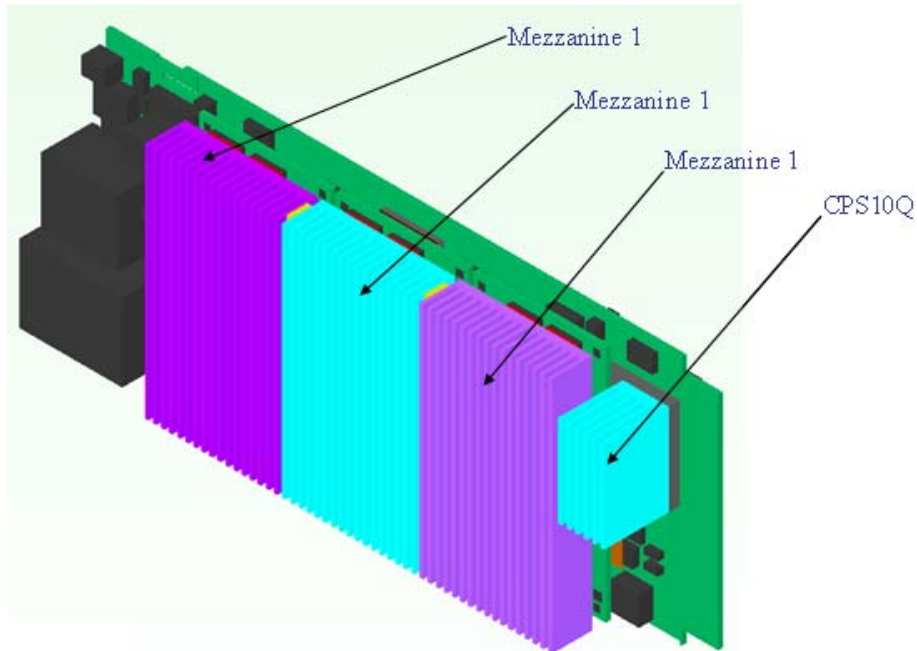


Figure 3-17. AMC Base Card and Heatsinks

3.18 Rapid Prototyping Systems

To aid future development, the MSC8156 AMC has been designed around a mezzanine concept to enable system concepts to be quickly realized using Freescale’s QoreIQ and DSP products. The mezzanines that contain processor and memory functions provide the system building blocks, while the AMC base card provides the required SerDes and Ethernet switching infrastructure.

An example of systems available is described in [Figure 3-18](#). Please contact Freescale for further details on these systems.

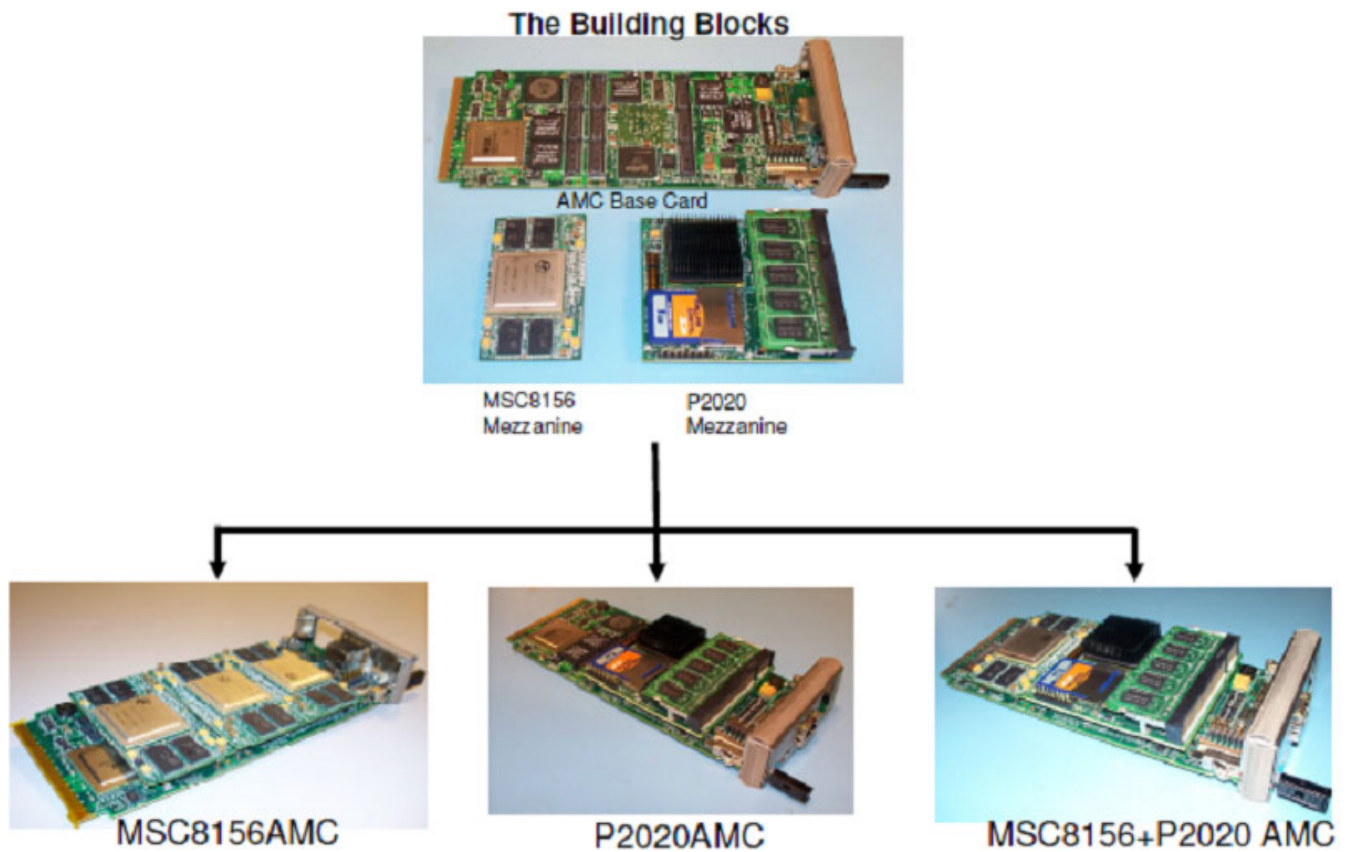


Figure 3-18. Rapid Prototyping Systems

Appendix A

JTAG Configuration File Listing

The listing below describes the CodeWarrior JTAG configuration file and the assignment of JTAG ID to the physical core.

```
# JTAG CHAIN for MS8156AMC
```

```
MSC8156 # DSP 3
```

```
MSC8156 # DSP 2
```

```
MSC8156 # DSP 1
```

```
# ID 0 : DSP3: Core 0
```

```
# ID 1 : DSP3: Core 1
```

```
# ID 2 : DSP3: Core 2
```

```
# ID 3 : DSP3: Core 3
```

```
# ID 4 : DSP3: Core 4
```

```
# ID 5 : DSP3: Core 5
```

```
# ID 6 : DSP2: Core 0
```

```
# ID 7 : DSP2: Core 1
```

```
# ID 8 : DSP2: Core 2
```

```
# ID 9 : DSP2: Core 3
```

```
# ID 10 : DSP2: Core 4
```

```
# ID 11 : DSP2: Core 5
```

```
# ID 12 : DSP1: Core 0
```

```
# ID 13 : DSP1: Core 1
```

```
# ID 14 : DSP1: Core 2
```

```
# ID 15 : DSP1: Core 3
```

```
# ID 16 : DSP1: Core 4
```

```
# ID 17 : DSP1: Core 5
```



Appendix B

FRU Data

The FRU data described below is preprogrammed into the Atmel ATmega128 MMC and provides basic product and configuration information.

[Common Header]

Format Version = 1

[Board Info]

Format Version = 1

Language Code = en

Mfg Date/Time = 01/04/2009 00:00:00

Manufacturer = Freescale

Product Name = MSC8156AMC

Serial Number = 0000000000

Part Number = 'A '

Fru File Id = fru-info.inf

[Product Info]

Format Version = 1

Language Code = en

Manufacturer = Freescale

Product Name = MSC8156AMC

Part/Model Number = MSC8156AMC

Product Version = Rev 1.0

Serial Number = 0000000000

Asset Tag =

Fru File Id = fru-info.inf

FRU Data

[Module Current]

Format Version = 2

Vendor Format Version = 0

Current Draw = 5.0

[Amc Connectivity]

Format Version = 2

Vendor Format Version = 0

Resource = AMC

Channels = 0, 1, 4 5 6 7, 8 9 10 11

0,0 = AMC.2 Ethernet, 1000Base-BX

1,0 = AMC.2 Ethernet, 1000Base-BX

2,0 1 2 3 = AMC.4 Serial RapidIO, 2

3,0 1 2 3 = AMC.4 Serial RapidIO, 2

[Clock Configuration]

Format Version = 2

Vendor Format Version = 0

Resource = AMC

FCLKA = pci express:96:100M:90M:110M